



Department of Electronics and Communication Engineering

Master of Technology

Electronics and Communication Engineering

VLSI Design and Systems

Curriculum

University Vision

We visualize Graphic Era (Deemed to be University) as an internationally recognized, enquiry driven, ethically engaged diverse community, whose members work collaboratively for positive transformation in the world, through leadership in teaching, research and social action.

University Mission

The mission of the university is to promote learning in true spirit and offering knowledge and skills in order to succeed as professionals. The university aims to distinguish itself as a diverse, socially responsible learning community with a high-quality scholarship and academic rigor.

Department Vision

The Department visualizes itself to become leading centre of learning in the field of Electronics & Communication Engineering with academic excellence in research to produce self-motivated, creative, and socially responsible engineers and specialists, ready to take up challenges of industrial development with ethics and societal commitment.

Department Mission

M1: *To provide high quality contemporary education in the field of Electronics & Communication Engineering and professional ethics to its learners.*

M2: *To provide creative learning environment for the students to equip them with strong foundation for continuing higher education.*

M3: *To pursue research and develop insight knowledge of current and emerging technologies in Electronics & Communication Engineering to serve the needs of the society, industry, and scientific community.*

M4: *To prepare students to have creative and innovative thinking to develop them into socially responsible professionals*

Program Educational Objectives (PEOs):

<i>PEO 1</i>	<i>Implementation of core-engineering knowledge to solve practical problems in the areas of VLSI design and Systems, and to produce innovative systems in these domains.</i>
<i>PEO 2</i>	<i>Motivating entrepreneurship in VLSI domains by integration of sustainability with efficiently designed systems.</i>
<i>PEO 3</i>	<i>Sharpening the educational, and research-oriented skills of the students for their easy merger into a future career in research or academia.</i>
<i>PEO 4</i>	<i>Developing the design engineers with excellent ability to communicate, along with a morally responsible behavior.</i>

Program Outcomes (POs):

<i>PO1</i>	<i>Apply the knowledge of science, mathematics, and engineering principles for developing problem solving attitude.</i>
<i>PO2</i>	<i>Identify, formulate, and solve engineering problems in the broad areas like System Design using VLSI.</i>
<i>PO3</i>	<i>Use different modern engineering software tools in the domain of VLSI and Systems Design.</i>
<i>PO4</i>	<i>Design and conduct experiments, analyze and interpret data, imbibe programming skills for development of simulation experiments.</i>
<i>PO5</i>	<i>Function as a member of a multidisciplinary team with sense of ethics, integrity, and social responsibility.</i>
<i>PO6</i>	<i>Realize the need for self-education and ability for independent and life-long learning.</i>

Program Specific outcomes (PSOs):

<i>PSO1</i>	<i>Attain competency in areas of IC designing, testing, and developing prototype of various VLSI circuits.</i>
<i>PSO2</i>	<i>Integrating various VLSI sub-systems to design industrial circuits.</i>
<i>PSO3</i>	<i>Students gain skills in developing various complicated circuits and excel in industrial sector.</i>

Department of Electronics and Communication Engineering

Course Components of Postgraduate Programme

Definition of Credits

	<i>1 Hr. Lecture (L) per week</i>		<i>1 credit</i>
	<i>1 Hr. Tutorial (T) per week</i>		<i>1 credit</i>
	<i>1 Hr. Practical (P) per week</i>		<i>0.5 credit</i>
	<i>2 Hours Practical (P) per week</i>		<i>1 credit</i>
<i>S. No.</i>	<i>Category</i>	<i>Abbreviation</i>	<i>Break-up of credits (M. Tech-VLSI Design and Systems)</i>
<i>1.</i>	<i>Program Core</i>	<i>PC</i>	<i>34</i>
<i>2.</i>	<i>Program Elective courses relevant to chosen specialization/branch</i>	<i>PE</i>	<i>09</i>
<i>3.</i>	<i>Open subjects–Electives from other technical and/or emerging subjects</i>	<i>OE</i>	<i>03</i>
<i>4.</i>	<i>Project work, seminar and internship in industry or appropriate workplace/ academic and research institutions in India/abroad</i>	<i>PROJ</i>	<i>28</i>
<i>5.</i>	<i>General Proficiency*</i>	<i>GP</i>	<i>04</i>
		<i>Total</i>	<i>78</i>

***Institution Initiative**

Program Course Structure (All Semesters)

M. Tech (VLSI Design and Systems)

(Batch 2023 onwards)

Semester I

<i>Course Module</i>					<i>Teaching Periods</i>			<i>Weightage: Evaluation</i>			
<i>COURSE</i>											
<i>S. No.</i>	<i>Code</i>	<i>Course title</i>	<i>Component</i>	<i>Credits</i>	<i>L</i>	<i>T</i>	<i>P</i>	<i>CIE</i>	<i>MSE</i>	<i>SEE</i>	<i>Total</i>
1	VDM 101	<i>Semiconductor Materials and Devices</i>	<i>PC</i>	3	3	0	0	25	25	50	100
2	VDM 102	<i>CMOS Analog Circuit Design</i>	<i>PC</i>	3	3	0	0	25	25	50	100
3	VDM 103	<i>Advanced Digital Integrated Circuit</i>	<i>PC</i>	3	3	0	0	25	25	50	100
4	VDM 104	<i>VLSI Technology</i>	<i>PC</i>	3	3	0	0	25	25	50	100
5	VDM -- -	<i>Program Elective-I</i>	<i>PE</i>	3	3	0	0	25	25	50	100
<i>Laboratory and Others</i>											
6	VDM 151	<i>CMOS Analog Circuit Design Lab</i>	<i>PC</i>	2	0	0	4	25	25	50	100
7	VDM 152	<i>Digital VLSI Circuit Design Lab</i>	<i>PC</i>	2	0	0	4	25	25	50	100
8	GP101	<i>General Proficiency</i>	<i>GP</i>	1	0	0	0	0	0	100	100
TOTAL				20	15	00	08				800

M. Tech (VLSI Design and Systems)

(Batch 2023 onwards)

Semester II

Course Module					Teaching Periods			Weightage: Evaluation			
COURSE											
S. No.	Code	Course title	Component	Credits	L	T	P	CIE	MSE	SEE	Total
1	VDM 201	Advanced ASIC and FPGA Design	PC	3	3	0	0	25	25	50	100
2	VDM 202	Digital System Design using Verilog HDL	PC	3	3	0	0	25	25	50	100
3	VDM 203	Advanced VLSI Circuit Testing	PC	3	3	0	0	25	25	50	100
4	VDM 204	Low Power VLSI Design	PC	3	3	0	0	25	25	50	100
5	VDM _____	Program Elective-II	PE	3	3	0	0	25	25	50	100
Laboratory and Others											
6	VDM 251	Verilog HDL Lab	PC	2	0	0	4	25	25	50	100
7	VDM 252	VLSI Physical Design Lab	PC	2	0	0	4	25	25	50	100
8	VDM 253	Mini Project with Seminar	PROJ	2	0	0	4	25	0	75	100
9	GP 201	General Proficiency	GP	1	0	0	0	0	0	100	100
TOTAL				22	15	00	12				900

M. Tech (VLSI Design and Systems)

(Batch 2023 onwards)

Semester III

<i>Course Module</i>					<i>Teaching Periods</i>			<i>Weightage: Evaluation</i>			
<i>COURSE</i>											
<i>S. No.</i>	<i>Code</i>	<i>Course title</i>	<i>Component</i>	<i>Credits</i>	<i>L</i>	<i>T</i>	<i>P</i>	<i>CIE</i>	<i>MSE</i>	<i>SEE</i>	<i>Total</i>
1	VDM _____	Program Elective-III	PE	3	3	0	0	25	25	50	100
2	VOM _____	Open Elective	OE	3	3	0	0	25	25	50	100
<i>Laboratory and Others</i>											
3	VDM 351	Modelling and Simulation Lab	PC	2	0	0	4	25	25	50	100
4	VDM 301	Dissertation Phase-I*	PROJ	10	0	0	20	25	50	125	200
5	GP 301	General Proficiency	GP	1	0	0	0	0	0	100	100
		TOTAL		19	06	00	24				600

**Students going for Industrial Project/Thesis will complete these courses through MOOCs.*

M. Tech (VLSI Design and Systems)

(Batch 2023 onwards)

Semester IV

COURSE					Teaching Periods			Weightage: Evaluation			
S. No.	Code	Course title	Component	Credits	L	T	P	CIE	MSE	SEE	Total
1	VDM 401	Dissertation Phase-II	PROJ	16	0	0	32	50	100	250	400
2	GP 401	General Proficiency	GP	1	0	0	0	0	0	100	100
		TOTAL		17	00	00	32				500

M. Tech (VLSI Design and Systems)
(Batch 2023 onwards)
Program Electives and Open Electives

<i>Program Elective Courses</i>		
<i>Course Code</i>	<i>Course Name</i>	<i>Semester</i>
<i>Program Elective I</i>		
<i>VDM 191</i>	<i>Advanced Nanotechnology</i>	<i>First</i>
<i>VDM 192</i>	<i>Optimization Techniques in VLSI Design</i>	
<i>VDM 193</i>	<i>Theory and Application of Embedded Systems</i>	
<i>VDM 194</i>	<i>Digital Signal Processing for VLSI</i>	
<i>VDM 195</i>	<i>Robust Control System</i>	
<i>VDM 196</i>	<i>Control of Advanced Electric Machine</i>	
<i>Program Elective II</i>		
<i>VDM 291</i>	<i>Micro-Sensors and MEMS</i>	<i>Second</i>
<i>VDM 292</i>	<i>RF Microelectronics Devices</i>	
<i>VDM 293</i>	<i>VLSI Circuits for Biomedical Application</i>	
<i>VDM 294</i>	<i>Microwave & MM-wave Integrated Circuits and Applications</i>	
<i>VDM 295</i>	<i>Renewable Energy Resources and Energy Management</i>	
<i>VDM 296</i>	<i>Multivariable Control System</i>	
<i>Program Elective III</i>		
<i>VDM 391</i>	<i>Organic Electronics Devices and Circuits</i>	<i>Third</i>
<i>VDM 392</i>	<i>Memory Design and Testing</i>	
<i>VDM 393</i>	<i>System on Chip Design and Testing</i>	
<i>VDM 394</i>	<i>VLSI Physical Design Automation</i>	
<i>VDM 395</i>	<i>Power Quality Assessment</i>	
<i>VDM 396</i>	<i>Optimal & Adaptive Control</i>	

Open Elective Courses

<i>Course Code</i>	<i>Course Name</i>	<i>Semester</i>
<i>VOM 301</i>	<i>Cloud Computing</i>	<i>Third</i>
<i>VOM 302</i>	<i>Internet of Things</i>	
<i>VOM 303</i>	<i>Artificial Intelligence and expert systems</i>	
<i>VOM 304</i>	<i>Soft Computing</i>	

Abbreviations:

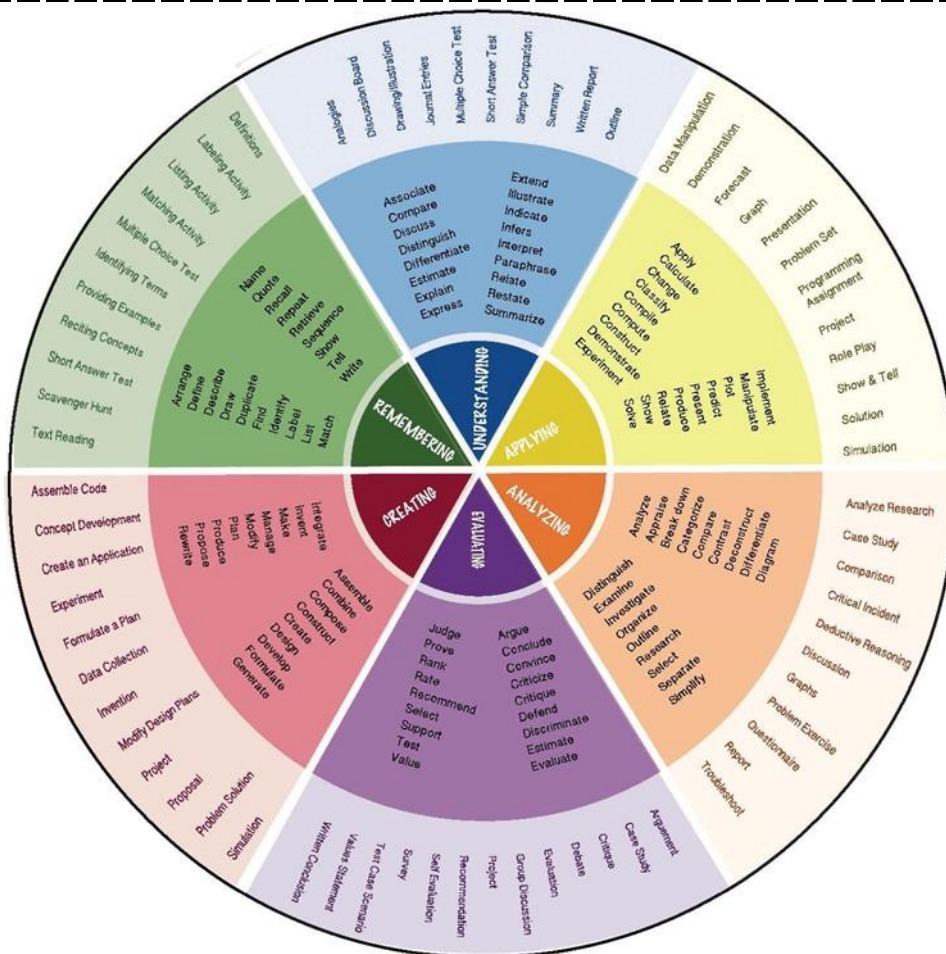
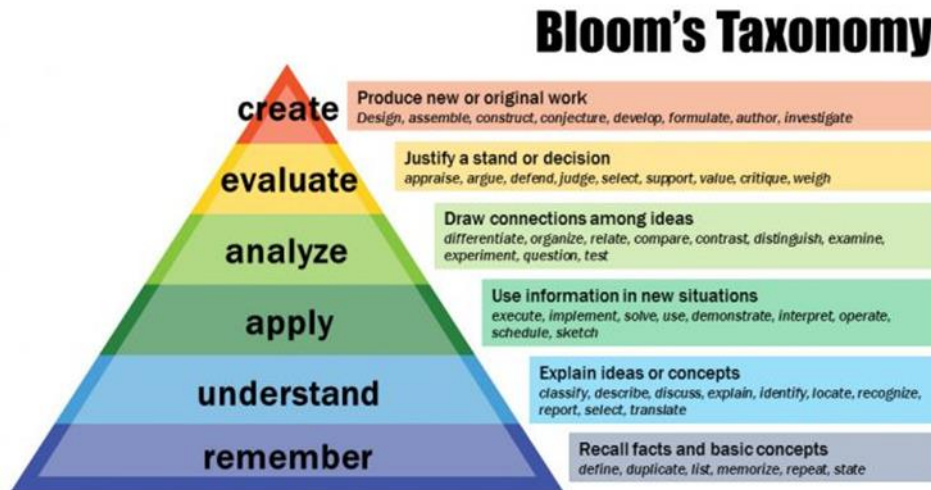
<i>L</i>	<i>Lecture</i>
<i>T</i>	<i>Tutorial</i>
<i>P</i>	<i>Practical</i>
<i>CWA</i>	<i>Class Work Assessment</i>
<i>MSE</i>	<i>Mid Semester Exam</i>
<i>ESE</i>	<i>End Semester Exam</i>
<i>PC</i>	<i>Program Core</i>
<i>PE</i>	<i>Program Elective</i>
<i>OE</i>	<i>Open Elective</i>
<i>PROJ</i>	<i>Project</i>
<i>GP</i>	<i>General Proficiency*</i>

**Institution Initiative*

Bloom's Taxonomy for Curriculum Design and Assessment

Preamble

The design of curriculum and assessment is based on Bloom's Taxonomy. A comprehensive guideline for using Bloom's Taxonomy is given below for reference.



GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 101	Course Title		Semiconductor Materials and Devices		
2.	Contact Hours	L	3	T	0	P	0
3.	Examination Duration	Theory		3	Practical		0
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	03					
6.	Semester	First					
7.	Category of Course	PC					
8.	Pre-requisite	Basic Electronics Engineering (TEC-101/201), Electronic Devices and Circuits (TEC-301)					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Create basic understanding of semiconductor device physics.</p> <p>CO2: Evaluate two terminal MOS structure in terms of its electrical parameters.</p> <p>CO3: Analyse the three terminal MOS structure in terms of electrical potential and charge.</p> <p>CO4: Apply surface potential and charges in different regions of MOSFET operation.</p> <p>CO5: Understand the short channel and narrow channel effects.</p> <p>CO6: Implement the concepts of semiconductor device physics in developing real life applications.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Basics of Semiconductors: Semiconductor materials, Energy levels, Intrinsic and extrinsic semiconductor, Equilibrium in absence/presence of electric field.	8
2.	Unit 2: PN Junction Diode: Junction diode: PN junction, Tunnel diode, Quasi-fermi levels, Depletion width capacitance and its application in doping profile determination, I-V characteristics of narrow and wide base diodes and their equivalent circuits, Breakdown mechanisms, Small signal ac impedance.	8
3.	Unit 3: Two Terminal MOS Structure:	10

	<i>Flat band voltage, Potential balance and charge balance, Effect of gate body voltage on surface condition, Accumulation, Depletion, Inversion, General analysis, Small signal capacitance.</i>	
4.	Unit 4: Three Terminal MOS Structure: <i>Contacting the inversion layer, Body effect, Different regions of operation, Pinch-off voltage.</i>	10
5.	Unit 5: Four Terminal MOS Structure: <i>Transistors regions of operation, Complete all-region model, Simplified all-region model, Models based on quasi fermi potential, Regions of inversion in terms of terminal voltage, Temperature effects, Breakdown, Enhancement mode, Depletion mode transistors.</i>	6
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	Tsividis, Yannis, and Colin McAndrew, " Operation and Modelling of the MOS Transistor ", Oxford: Oxford University Press, Vol. 2, 3 rd Edition, 2003.	3 rd	2003
2.	S. Kang and Y. Leblebici, " CMOS Digital Integrated Circuits, Analysis and Design ", 3 rd Edition, Tata McGraw-Hill, 2003.	3 rd	2003
	Reference Books		
1.	Adel S. Sedra, Kenneth C. Smith, " Microelectronic Circuits ", Oxford University Press	7 ^h	2014
2.	S. Salivahanan and S. Arivazhagan, " Digital Circuits and Design ", Oxford University Press,	5 th	2008
3.	Robert L. Boylestad and Louis Nashelsky, " Electronic Devices and Circuit Theory ", Prentice Hall of India (PHI).	9 th	2006

12.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	<i>Department of Electronics and Communication Engineering</i>							
1.	<i>Subject Code</i>	<i>VDM 102</i>		<i>Course Title</i>		<i>CMOS Analog Circuit Design</i>		
2.	<i>Contact Hours</i>	<i>L</i>	<i>3</i>	<i>T</i>	<i>0</i>	<i>P</i>	<i>0</i>	
3.	<i>Examination Duration</i>	<i>Theory</i>		<i>3</i>		<i>Practical</i>		<i>0</i>
4.	<i>Relative Weight</i>	<i>CIE</i>	<i>25</i>	<i>MSE</i>	<i>25</i>	<i>SEE</i>	<i>50</i>	
6.	<i>Credit</i>	<i>03</i>						
6.	<i>Semester</i>	<i>First</i>						
7.	<i>Category of Course</i>	<i>PC</i>						
8.	<i>Pre-requisite</i>	<i>Electronics Devices and Circuits (TEC 301)</i>						

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Recall the knowledge of analog IC design in CMOS technologies.</p> <p>CO2: Understand MOS transistors with different configurations.</p> <p>CO3: Apply the concepts of multistage and differential MOS amplifiers.</p> <p>CO4: Analyse the current mirror circuits.</p> <p>CO5: Assess and evaluation the feedback amplifiers and phase locked loop.</p> <p>CO6: Design and develop various CMOS analog circuits.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Models for Integrated Circuit Active Devices: <i>The depletion region of a PN junction, Depletion region capacitance and junction breakdown, Basics of MOS transistor, Derivation of current-voltage relationship, Analysis of MOS as an amplifier, Small signal models of MOS transistor, MOS transistor frequency response.</i>	8
2.	Unit 2: Single Stage Amplifier: <i>Common source stage with resistive load, CS stage with diode connected load, CS stage with current source load, CS stage with triode load, CS stage with source generation, Source follower and common gate configuration.</i>	9
3.	Unit 3: Multistage Amplifier and Operational Amplifier: <i>Cascode current source, Cascode amplifier, Differential pair, Small and large signal analysis of differential amplifier, Differential amplifier with MOS loads, OPAMP design: General consideration, One stage OpAmp</i>	9
4.	Unit 4: Current Mirrors, Active Loads and References:	9

	<i>Simple current mirror, Cascode current mirror, Wilson current mirror, Common source amplifier with complementary load, Voltage and current references: Widlar and peaking current sources, supply insensitive biasing</i>	
5.	Unit 5: Feedback and Non-Linear Analog Circuits: <i>General consideration, Properties of feedback circuits, Feedback configuration, Nonlinear analog circuits: LC oscillators, Simple phase locked loop.</i>	9
	Total	44

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	<i>B. Razavi, Design of analog CMOS Integrated Circuits, McGraw-Hill</i>	1 st	2002
2.	<i>Mohammed Ismail and Terri Faiz, Analog VLSI Signal and Information Process, McGraw-Hill.</i>	1 st	1994
	Reference Books		
1.	<i>Paul R. Gray and R. G. Meyer, Analysis and Design of Analog Integrated Circuits, John Wiley and Sons</i>	4 th	2001
2.	<i>R. Jacob Baker, H. W. Li, and D.E. Boyce, CMOS: Circuit Design, Layout and Simulation, Prentice-Hall of India</i>	3 rd	2010

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 103		Course Title		Advanced Digital Integrated Circuit	
2.	Contact Hours	L	3	T	0	P	0
3.	Examination Duration	Theory		3		Practical	0
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	03					
6.	Semester	First					
7.	Category of Course	PC					
8.	Pre-requisite	Basic Electronics Engineering and Digital Electronics					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Describe the basic MOS structure and layout design</p> <p>CO2: Understand the static and dynamic characteristics of MOS inverters</p> <p>CO3: Apply the MOS concepts to design combinational and sequential MOS logic circuits.</p> <p>CO4: Analyze different digital MOS logic circuits.</p> <p>CO5: Estimate power consumption of CMOS logic circuits.</p> <p>CO6: Integrate various concepts of digital VLSI circuit design and apply them in designing of MOS based digital circuits.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Introduction and Implementation of strategies for digital ICs: Issues in Digital Integrated Circuit Design, Quality Metrics of a Digital Design, Design rule: Stick diagram and layout. Custom Circuit design, Cell based, and Array based design implementations.	10
2.	Unit 2: MOS Inverters: Static and Dynamic Characteristics of CMOS inverter, Power dissipation, Logical effort.	10
3.	Unit 3: Designing combinational and sequential circuits: Static CMOS design, Different styles of logic circuits, Logical effort of complex gates, Static and dynamic properties of complex gates, Dynamic CMOS Logic. Timing metrics of sequential circuits, Dynamic latches and Registers. Pipelining.	10
4.	Unit 4: Interconnect and Timing Issues: Circuit characterization and performance estimation - Resistance, Capacitance estimation - Switching characteristics - Delay models -Timing issues in Digital circuits, Power dissipation. Impact of Clock Skew and Jitter.	6
5.	Unit 5: Memory Design:	6

	<i>Read-Only Memories, ROM cells, Read-write memories (RAM), dynamic memory design, 6 transistor SRAM cell, Sense amplifiers</i>	
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	<i>S. Kang and Y. Leblebici, "CMOS Digital Integrated Circuits, Analysis and Design", Tata McGraw-Hill.</i>	3rd	2003
2.	<i>J. M. Rabaey, A. Chandrakasan and B. Nikolic, "Digital Integrated Circuits: A Design Perspective", Prentice-Hall of India.</i>	2nd	2006
	Reference Books		
1.	<i>John P. Uyemura, "Introduction to VLSI Circuits", Wiley India Pvt. Ltd.</i>	1st	2012
2.	<i>Eugene Fabricius, "Introduction to VLSI Design", New Ed Edition, Tata McGraw - Hill Education.</i>	1st	1990
3.	<i>N. H. E. Weste et. al., "CMOS VLSI Design", Pearson.</i>	3rd	2005
4.	<i>R. Jacob Baker, "CMOS: circuit design, layout, and simulation", John Wiley & Sons,</i>	3rd	2010

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	<i>Department of Electronics and Communication Engineering</i>						
1.	<i>Subject Code</i>	<i>VDM 104</i>		<i>Course Title</i>		<i>VLSI Technology</i>	
2.	<i>Contact Hours</i>	<i>L</i>	<i>3</i>	<i>T</i>	<i>0</i>	<i>P</i>	<i>0</i>
3.	<i>Examination Duration</i>	<i>Theory</i>		<i>3</i>		<i>Practical</i>	<i>0</i>
4.	<i>Relative Weight</i>	<i>CIE</i>	<i>25</i>	<i>MSE</i>	<i>25</i>	<i>SEE</i>	<i>50</i>
6.	<i>Credit</i>	<i>03</i>					
6.	<i>Semester</i>	<i>First</i>					
7.	<i>Category of Course</i>	<i>PC</i>					
8.	<i>Pre-requisite</i>	<i>Basic Electronics Engineering and Digital Electronics</i>					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Explain about wafer fabrication techniques and oxidation process</p> <p>CO2: Analyse photolithography and etching techniques of VLSI design.</p> <p>CO3: Extend the knowledge of different physical and chemical deposition methods.</p> <p>CO4: Investigate metal deposition techniques and IC fabrication methodologies.</p> <p>CO5: Design and analysis of different packaging methods.</p> <p>CO6: Create a base for the semiconductor device fabrication using VLSI technology.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Wafer Preparation and Oxidation: <i>Electron grade silicon, Crystal growth, Wafer preparation, Processing considerations, Vapor phase epitaxy and molecular beam epitaxy, Film characteristics, SOI structure, Oxide formation, Kinetics, Oxidation systems, Dry and wet oxidation, Masks properties of SiO₂, Oxidation defects, Redistribution of dopant at interface, Oxidation of poly silicon.</i>	10
2.	Unit 2: Lithography and Etching: <i>Optical, Electron, X-Ray and Ion Lithography methods, Positive and negative photo resist. Plasma properties, Size, Control, Etch mechanism, Etch techniques and equipment.</i>	8
3.	Unit 3: Deposition and diffusion: <i>Deposition process and methods, Diffusion in solids, Diffusion equation and Diffusion mechanisms, Flick's one-dimensional diffusion equation, Atomic diffusion mechanism, Measurement techniques, Range theory, Implant equipment, Ion implantation, Damage and annealing, Ion implantation systems.</i>	8
4.	Unit 4: Metallization and IC Fabrication: <i>Metallization and its applications, Process simulation of Ion implementation, Diffusion, Oxidation, Epitaxy, Lithography, Etching and deposition, Annealing shallow junction –</i>	8

	<i>High energy implantation, Physical vapours deposition patterning. NMOS, CMOS and bipolar IC technologies and IC fabrication.</i>	
5.	Unit 5: Packaging: <i>Analytical and assembly techniques and packaging of VLSI devices.</i>	8
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	S. M. Sze, "VLSI Technology", McGraw Hill, 2nd Edition, 1988.	2 nd	1988
2.	W. Wolf, "Modern VLSI Design", Pearson, 3rd Edition, 2002.	3 rd	2002
	Reference Books		
1.	S. K. Gandhi, "VLSI Fabrication Principles Silicon and Gallium Arsenide", Wiley-INDIA, 2nd Edition, 1994.	2 nd	1994
2.	Wai Kai Chen, "VLSI Technology", CRC press, 1st Edition, 2003.	1 st	2003

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 151		Course Title	CMOS Analog Circuit Design Lab		
2.	Contact Hours	L	0	T	0	P	4
3.	Examination Duration	Theory		0	Practical		4
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	02					
6.	Semester	First					
7.	Category of Course	PC					
8.	Pre-requisite	Electronics Devices and Circuit, VLSI Technology and Design					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Understand Cadence Virtuoso simulation tool.</p> <p>CO2: Design common source, common drain, and operational amplifier using Cadence tool.</p> <p>CO3: Simulate and analyse various CMOS based circuits using Cadence tool.</p> <p>CO4: Integrate the acquired knowledge for developing CMOS based circuits.</p>
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10. Details of the Course

S. No.	List of problems for which student should develop program and execute in the Laboratory	Contact Hours
1.	Design a new cell view and build common source amplifier and create a symbol for the common source amplifier using 90 nm technology.	1
2.	Simulation of common source amplifier test circuit using common source amplifier symbol using 90 nm technology.	1
3.	Create a layout of common source amplifier using 90 nm technology.	2
4.	Design a new cell view and build common drain amplifier and create a symbol for the common drain amplifier using 90 nm technology.	1
5.	Simulation of common drain amplifier test circuit using common drain amplifier symbol using 90 nm technology.	1
6.	Create a layout of common drain amplifier using 90 nm technology.	2

7.	Design a new cell view and build Differential amplifier and create a symbol for the Differential amplifier using 90 nm technology.	1
8.	Simulation of Differential amplifier test circuit using Differential amplifier symbol using 90 nm technology.	1
9.	Create a layout of Differential amplifier using 90 nm technology.	2
10.	Design a new cell view and build operational amplifier and create a symbol for the operational amplifier using 90 nm technology.	1
11.	Simulation of operational amplifier test circuit using operational amplifier symbol using 90 nm technology.	1
12.	Create a layout of operational Amplifier using 90 nm technology.	2
	Total	16
Innovative Experiments		
13.	Design and simulation of current mirror circuits using 90 nm technology.	2
14.	Design and Simulation of Cascode amplifier using 90 nm technology.	2
	Total	04

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	B. Razavi, Design of analog CMOS Integrated Circuits, McGraw-Hill	1 st	2002
2.	Paul R. Gray and R. G. Meyer, Analysis and Design of Analog Integrated Circuits, John Wiley and Sons	4 th	2001
3.	Mohammed Ismail and Terri Faiz, Analog VLSI Signal and Information Process, McGraw-Hill	1 st	1994
	Reference Books		
1.	R. Jacob Baker, H. W. Li, and D.E. Boyce, CMOS: Circuit Design, Layout and Simulation, Prentice-Hall of India, 3rd Edition, 2010.	3 rd	2010

12.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 152		Course Title		Digital VLSI Circuit Design Lab	
2.	Contact Hours	L	0	T	0	P	4
3.	Examination Duration	Theory		0		Practical	
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	02					
6.	Semester	First					
7.	Category of Course	PC					
8.	Pre-requisite	Digital Electronics					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Understand the CMOS based digital integrated circuits</p> <p>CO2: Analyze CMOS based combinational circuits using 180nm Technology</p> <p>CO3: Evaluate CMOS based sequential circuits and memory devices.</p> <p>CO4: Design and validate various CMOS based digital circuits using Cadence tool</p>
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10. Details of the Course

S. No.	List of problems for which student should develop program and execute in the Laboratory	Contact Hours
1.	Design and comparison of DC and transient output characteristics of CMOS inverter at different aspect ratio.	2
2.	Draw a layout of CMOS inverter using 45 nm technology and check for LVS and DRC for inverter circuit.	2
3.	Design and implement various gates with CMOS logic along with its layout.	2
4.	Draw a schematic of half adder/full adder using 45 nm technology and analyse its transient characteristics.	2
5.	Draw the layouts of half adder/full adder using 45 nm technology and simulate its transient characteristics.	2
6.	Design a schematic of comparator using 45 nm technology and simulate its transient characteristics	2
7.	Design and Implementation of 2:1 Multiplexer and 1:2 Demultiplexer.	2

8.	<i>Design the schematic of latches using 45 nm technology and simulate its transient characteristics</i>	2
9.	<i>Design the schematic of flip-flops using 45 nm technology and simulate its transient characteristics</i>	2
10.	<i>Design the schematic of shift register using 45 nm technology and simulate its transient characteristics</i>	2
11.	<i>Design the schematic of up/down counter using 45 nm technology and simulate its transient characteristics</i>	2
12.	<i>Design the schematic of 6T RAM using 45 nm technology and simulate its transient characteristics</i>	2
	Total	24
<i>Innovative Experiments</i>		
13.	<i>Design and implementation of Flash Memory with Cadence tool.</i>	2
14.	<i>Design and implementation of Different Analog to Digital converter (ADC) with Cadence tool.</i>	2
15.	<i>Simulate substrate bias (Body) effect in CMOS inverter.</i>	2
	Total	06

11.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 201	Course Title		Advanced ASIC and FPGA Design		
2.	Contact Hours	L	3	T	0	P	0
3.	Examination Duration	Theory		3	Practical		0
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	03					
6.	Semester	Second					
7.	Category of Course	PC					
8.	Pre-requisite	Advanced Digital Integrated Circuit					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Describe the concepts of ASICs, CMOS Logic and ASIC Library Design.</p> <p>CO2: Understanding about partitioning, floor planning, placement and routing including circuit extraction of ASIC.</p> <p>CO3: Applying the concepts of ASIC and FPGA in designing various architecture of different types of FPGA.</p> <p>CO4: Analysis of the issues involved in ASIC design, including technology choice, design management, tool-flow, verification, debug and test, as well as the impact of technology scaling on ASIC design.</p> <p>CO5: Evaluation of SOC based integrated circuits for various FPGA applications.</p> <p>CO6: Designing of ASIC family using Xilinx tool to optimize the device performance.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Introduction: Types of ASICs, Design flow, CMOS transistors CMOS design rules, Combinational logic cell, Sequential logic cell, Transistors as resistors, Transistor parasitic capacitance, Logical effort, Library cell design, Library architecture.	10
2.	Unit 2: ASIC Physical Design: System partition, partitioning, partitioning methods, interconnect delay models and measurement of delay, floor planning, placement, Routing, Circuit extraction, Design Rule Check.	9
3.	Unit 3: FPGA Architecture: Field Programmable gate arrays, Logic blocks, routing architecture, Design flow technology, Xilinx XC4000, ALTERA's FLEX 8000/10000, ACTEL's ACT-1,2,3 and their speed performance Case studies: Altera MAX 5000 and 7000, Altera MAX 9000, Spartan II and Virtex II FPGAs.	10

4.	Unit 4: Trade off issues at System Level: Optimization with regard to speed, area and power; asynchronous and low power system design. ASIC physical design issues, System Partitioning, Power Dissipation, Partitioning Methods.	8
5.	Unit 5: System on Chip Design: Design using Xilinx Family, System on Chip Design, SoC Design Flow, Platform based and IP based SoC designs, Basic Concept of Bus – Based communication architectures, On- chip communication architectures standards, Low power SoC designs.	8
	Total	45

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	Pasricha and N. Dutt, “ On-Chip Communication Architectures System on Chip Interconnect ”, Elseveir.	1 st	2008
2.	Michael John Sebastian Smith, “ Application-Specific Integrated Circuits ”, Addison-Wesley VLSI Systems Series	1 st	2008
	Reference Books		
1.	M. Rabaey, A. Chandrakasan, and B.Nikolic, “ Digital Integrated Circuit Design Perspective ”, Wiley.	2 nd	2003
2.	Hoi-Jun Yoo, Kangmin Lee and Jun Kyong Kim, “ Low-Power NoC for High-Performance SoC Design ”, CRC Press.	1 st	2008

12.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	<i>Department of Electronics and Communication Engineering</i>						
1.	<i>Subject Code</i>	<i>VDM 202</i>		<i>Course Title</i>		<i>Digital System Design using Verilog HDL</i>	
2.	<i>Contact Hours</i>	<i>L</i>	<i>3</i>	<i>T</i>	<i>0</i>	<i>P</i>	<i>0</i>
3.	<i>Examination Duration</i>	<i>Theory</i>		<i>3</i>		<i>Practical</i>	<i>0</i>
4.	<i>Relative Weight</i>	<i>CIE</i>	<i>25</i>	<i>MSE</i>	<i>25</i>	<i>SEE</i>	<i>50</i>
6.	<i>Credit</i>	<i>03</i>					
6.	<i>Semester</i>	<i>Second</i>					
7.	<i>Category of Course</i>	<i>PC</i>					
8.	<i>Pre-requisite</i>	<i>Digital Electronics</i>					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Describe digital circuits and its implementation through Verilog HDL code.</p> <p>CO2: Understand the concept of logic synthesis using Verilog HDL, and its impact in verification.</p> <p>CO3: Design various combinational and sequential circuits.</p> <p>CO4: Analyse user defined primitives in Verilog HDL.</p> <p>CO5: Apply the knowledge of different types of digital modelling in Verilog HDL.</p> <p>CO6: Justify the implementation of Verilog code of several digital circuits using Verilog HDL and their test benches.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	<p>Unit 1: Basic Concepts: <i>Lexical conventions, Data types, System tasks and compiler directives.</i></p> <p>Modules and Ports: <i>Modules, Ports, Hierarchical names.</i></p> <p>Gate-Level Modeling: <i>Gate types, Gate delays.</i></p>	8
2.	<p>Unit 2: Dataflow Modelling: <i>Continuous assignments, Delays, Expressions, Operators and Operands. Operator types, Examples.</i></p> <p>Behavioural Modelling: <i>Structured procedures, Procedural assignments, Timing controls, Conditional statements, Multiway branching, Loops, Sequential and parallel Blocks, Generate blocks, Examples.</i></p>	10
3.	<p>Unit 3: Task and Functions: <i>Differences between tasks and functions, Tasks, Functions.</i></p> <p>Useful Modelling Techniques:</p>	8

	<i>Procedural continuous assignments, Overriding parameters, Conditional compilation and execution, Time scales, Useful system tasks.</i> Timing and Delays: <i>Types of delay models, Path delay modelling, Timing checks, Delay back-annotation.</i>	
4.	Unit 4: Switch-Level Modelling: <i>Switch-Modelling elements, examples.</i> User-Defined Primitives: <i>UDP basics, Combinational UDPs, Sequential UDPs, UDP table shorthand symbols, Guidelines for UDP design.</i>	8
5.	Unit 5: Writing Test Benches: <i>Basic test benches, Test bench structure, Constrained random stimulus generation, Object-oriented programming and Assertion-based verification.</i>	8
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	Samir Palnitkar, " Verilog HDL ", Pearson Education	2 nd	2003
2.	Mark Zwolinski, " Digital System Design with System Verilog ", Pearson Education	1 st	2009
	Reference Books		
1.	J. Bhasker, " Verilog HDL Synthesis-A practical Primer ", Star galaxy Press	1 st	1998
2.	J. Bhasker, " Verilog HDL Primer ", Pearson Education"	3 rd	2015

12.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	<i>Department of Electronics and Communication Engineering</i>							
1.	<i>Subject Code</i>	<i>VDM 203</i>		<i>Course Title</i>		<i>Advanced VLSI Circuit Testing</i>		
2.	<i>Contact Hours</i>	<i>L</i>	<i>3</i>	<i>T</i>	<i>0</i>	<i>P</i>	<i>0</i>	
3.	<i>Examination Duration</i>	<i>Theory</i>		<i>3</i>		<i>Practical</i>		<i>0</i>
4.	<i>Relative Weight</i>	<i>CIE</i>	<i>25</i>	<i>MSE</i>	<i>25</i>	<i>SEE</i>	<i>50</i>	
6.	<i>Credit</i>	<i>03</i>						
6.	<i>Semester</i>	<i>Second</i>						
7.	<i>Category of Course</i>	<i>PC</i>						
8.	<i>Pre-requisite</i>	<i>VLSI Technology</i>						

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Recall the knowledge of fault modeling and fault simulation.</p> <p>CO2: Understand ATPG algorithm for combinational and sequential circuits</p> <p>CO3: Apply the knowledge of high-level testability Measures, SCOAP controllability and observability.</p> <p>CO4: Analyze different memory testing algorithms</p> <p>CO5: Assess and evaluate scan architecture</p> <p>CO6: Design testing algorithms for VLSI components</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	<p>Unit 1: Introduction: Role of testing, Digital and analog VLSI testing, VLSI technology trends affecting testing.</p> <p>VLSI Testing Process and Test Equipment: Types of testing, Automatic test equipment, Multi-Site testing, Electrical parametric testing.</p> <p>Test Economics and Product Quality: Defining costs, Production benefit-cost analysis, Economics of testable design, The rule of ten, Yield, Test data analysis.</p> <p>Fault Modelling: Defects, Errors and Faults, Functional versus Structural testing, A glossary of fault models, Single stuck-at fault,</p> <p>Logic and Fault Simulation: Simulation for design verification, Simulation for test evaluation.</p>	10
2.	<p>Unit 2: Testability Measures: SCOAP controllability and observability, High-level testability measures.</p> <p>Combinational Circuit Test Generation: Algorithms and representations, Redundancy identification (RID), Testing as a global problem, Definitions, Test generation systems, Test compaction, Significant combinational ATPG algorithms and sequential circuit test generation.</p>	8

3.	Unit 3: Memory Test: <i>Memory density and defect trends, Faults, Memory test levels, March test notation, Fault modelling, Memory testing. Analog and mixed signal test, Delay test and IDDQ test.</i>	8
4.	Unit 4: Fundamental Techniques for Logic Testing: <i>DFT fundamentals, ATPQ fundamental, Scan architecture and technique</i>	8
5.	Unit 5: Embedded Core Test Fundamentals: <i>Introduction to embedded core testing, Core, Core-based design, Reuse core deliverables, Core DFT issues, Development of reusable core, Scan testing the isolated core, Scan testing the non-core logic, User defined logic chip-level DFT concerns, Memory testing with BIST.</i>	8
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	<i>Viswani D. Agarval Michael L. Bushnell, Essentials of electronic testing for digital memory & mixed signal VLSI circuit, Kluwer Academic Publications</i>	1 st	1999
2.	<i>Alfred L. Crouch, Design for test for digital IC's and embedded core systems, PHI</i>	1 st	1999
	Reference Books		
1.	<i>Parag. K. Lala, Digital circuit testing and testability, Academic Press</i>	1 st	1997
2.	<i>Ashok K. Sharma, Semiconductor memories technology, testing and reliability, Prentice-Hall of India Private Limited, New Delhi</i>	1 st	1997

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 204		Course Title		Low Power VLSI Design	
2.	Contact Hours	L	3	T	0	P	0
3.	Examination Duration	Theory		3		Practical	
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	03					
6.	Semester	Second					
7.	Category of Course	PC					
8.	Pre-requisite	Advanced Digital Integrated Circuit					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Acquire the fundamental knowledge of low power VLSI design,</p> <p>CO2: Infer about static and dynamic power dissipation.</p> <p>CO3: Ability to implement logic circuits and advanced low power design techniques.</p> <p>CO4: Analyse different techniques required to minimize the leakage power.</p> <p>CO5: Evaluate the characteristics low power analog and digital circuits.</p> <p>CO6: Design of low power memory devices.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Introduction to Low Power VLSI: Overview, Need for Low Power VLSI Digital Integrated Circuits, Basic Principles of Low Power Design, Physics of Power Dissipation; Technology and Device Effect on Low Power: Transistor Sizing, Gate Oxide Thickness, Impact of Technology Scaling, Technology & Device innovation.	8
2.	Unit 2: Sources of Power Dissipation in MOS Devices: Power Estimation, Dynamic Power Dissipation: Short Circuit Power, Switching Power, Gliching Power; Static Power Dissipation, Probabilistic Power Analysis, Degrees of Freedom.	10
3.	Unit 3: Logic Circuits and Advanced Techniques: Logic circuits, Special Techniques: Architecture and Systems; Emerging Low power Techniques, Physics of Power Dissipation in CMOS FET Devices; Design of Low Power CMOS Circuits, Supply Voltage Scaling Approaches; Switched Capacitance minimization Approaches.	8
4.	Unit 4: Leakage Power Minimization Approaches: Synthesis in Low Power Design, Test of Low Voltages CMOS Circuits; Variable threshold Voltage CMOS (VTCMOS) Approach, Multi threshold Voltage CMOS (MTCMOS)	8

	<i>approach, Power gating Transistor Stacking, Dual- threshold Voltage (V_t) Assignment Approach (DTCMOS).</i>	
5.	Unit 5: Low Power Techniques: <i>Low Power Static RAM Architectures, Low Power SRAM/DRAM Design, Low Energy Computing using Energy Recovery Techniques, Software Design for Low Power, CAD Tools for Low Power Synthesis.</i>	8
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	Gary Yeap, " Practical Low Power Digital VLSI Design ", Springer.	1 st	1998
2.	Kaushik Roy and Sharat Prasad, " Low Power CMOS VLSI Circuit Design " Wiley.	1 st	2000
	Reference Books		
1.	J. B. Kuo and J. H. Lou, Low " Voltage CMOS VLSI Circuits ", Wiley.	1 st	1999
2.	J. M. Rabaey, A. P. Chandrakasan and B. Nikolic, " Digital Integrated Circuits: A Design Perspective ",	2 nd	2003

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 251		Course Title		Verilog HDL Lab	
2.	Contact Hours	L	0	T	0	P	4
3.	Examination Duration	Theory		0		Practical	
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	02					
6.	Semester	Second					
7.	Category of Course	PC					
8.	Pre-requisite	Digital Electronics					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Understand digital circuit designing through Verilog HDL.</p> <p>CO2: Implement digital logic circuits using Verilog HDL in FPGA.</p> <p>CO3: Analyse various combinational and sequential circuits using Verilog HDL simulation codes.</p> <p>CO4: Design various digital systems using Verilog HDL simulation codes..</p>
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10. Details of the Course

S. No.	List of problems for which student should develop program and execute in the Laboratory	Contact Hours
1.	Design and simulation of XOR gate using NAND gate only.	2
2.	Design and simulation of comparator.	2
3.	Design and simulation of Full Adder and Full Subtractor.	2
4.	Design and simulation of Multiplexer and Demultiplexer.	2
5.	Design and simulation of Encoder and Decoder.	2
6.	Design and simulation of SR Flip-Flops and D Flip-flop.	2
7.	Design and simulation of JK Flip-Flops and T Flip-flop.	2
8.	Design and simulation of UP-DOWN counter/Decade counter.	2
9.	Design and simulation of different registers.	2
10.	Design and simulation of bidirectional and universal shift register	2
11.	Design and simulation of binary multiplier.	2
12.	FPGA Implementation of basics logic gates.	2
13.	Design and simulation of Finite State Machine (FSM) using "Function" in Verilog.	2

14.	<i>Design and simulation of Finite State Machine (FSM) without using "Function" in Verilog.</i>	2
	Total	28
<i>Innovative Experiments</i>		
13.	<i>FPGA Implementation of Flip-flops.</i>	2
14.	<i>FPGA Implementation of binary multiplier.</i>	2
15.	<i>Design and simulation of floating-point divider.</i>	2
16.	<i>As suggested by faculty and lab in-charge.</i>	2
	Total	08

11.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 252		Course Title		VLSI Physical Design Lab	
2.	Contact Hours	L	0	T	0	P	4
3.	Examination Duration	Theory		0		Practical	
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	02					
6.	Semester	Second					
7.	Category of Course	PC					
8.	Pre-requisite	Digital Electronics, Advanced Digital Integrated Circuit					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Understand Linux environment, tools, and basic scripting.</p> <p>CO2: Apply the concepts of physical design for VLSI chip.</p> <p>CO3: Analyze placement, routing, and power Planning for different circuits.</p> <p>CO4: Design circuits using Verilog HDL, waveform Debugging, and synthesis</p>
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10. Details of the Course

S. No.	List of problems for which student should develop program and execute in the Laboratory	Contact Hours
1.	Familiarization with Linux environment, and basic scripting using Verilog HDL.	2
2.	Design, simulation, and test of an 8-bit counter with instructions using Verilog HDL.	2
3.	Synthesis of 8-bit counter circuit with instructions using Verilog HDL.	2
4.	Placement and power planning of 8-bit counter circuit in cadence digital implementation tool of 8-bit counter circuit.	2
5.	Routing of 8-bit counter circuit in cadence digital implementation tool in gpdk 90 technology.	2
6.	Design, simulation, and test of a Half adder with instructions using Verilog HDL.	2
7.	Synthesis of Half adder circuit with instructions using Verilog HDL.	2
8.	Placement and power planning of Half adder circuit in Cadence digital implementation tool of Half adder circuit.	2
9.	Routing of Half adder circuit in Cadence digital implementation tool in gpdk 90 nm technology.	2
10.	Design, simulation, and test of a Full adder with instructions using Verilog HDL.	2

11.	<i>Design, simulation, and test of a Half subtractor with instructions using Verilog HDL.</i>	2
12.	<i>Synthesis of Half subtractor circuit with instructions using Verilog HDL.</i>	2
	Total	24
<i>Innovative Experiments</i>		
13.	<i>Design, simulation, and test of a Full subtractor with instructions using Verilog HDL.</i>	2
14.	<i>Routing of Full subtractor Circuit in Cadence Digital Implementation tool in gpdk 90 nm technology.</i>	2
15.	<i>Design, simulation, and Test of a Full subtractor with instructions using Verilog HDL.</i>	2
	Total	06

11.	<i>Mode of Evaluation</i>	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER III

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 351		Course Title		Modelling and Simulation Lab	
2.	Contact Hours	L	0	T	0	P	4
3.	Examination Duration	Theory		0		Practical	
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	02					
6.	Semester	Third					
7.	Category of Course	PC					
8.	Pre-requisite	Digital Electronics, Advanced Digital Integrated Circuit					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Understand various semiconductor devices and circuit using simulators</p> <p>CO2: Compute the characteristics of various digital and analog systems.</p> <p>CO3: Analyze Cadence, VTCAD and Xilinx tools for the implementation of digital and analog circuits</p> <p>CO4: Evaluate various MOS devices performance using MATLAB and VTCAD</p>
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10. Details of the Course

S. No.	List of problems for which student should develop program and execute in the Laboratory	Contact Hours
1.	Study of Cadence tool for the implementation of Multistage Amplifier.	2
2.	Study of Cadence tool for the implementation of analog circuits (CS Amplifier).	2
3.	Implementation of a novel circuit and its performance analysis using Cadence tool (Flip-Flops using pass transistors).	2
4.	Design and simulation of CMOS (NMOS/PMOS) using VTCAD and their characteristics analysis.	2
5.	Design and simulation of Dual Gate MOSFET using VTCAD and their characteristics analysis.	2
6.	Design and simulation of Gate All Around FET (GAA-FET) using VTCAD and their characteristics analysis.	2
7.	Design and simulation of BJT using VTCAD and their characteristics analysis.	2
8.	Study of OrCAD tool for analysis of RC coupled amplifier.	2
9.	To plot the drain characteristics for n-channel MOSFET using MATLAB for implementation of MOSFET models in linear and saturation region.	2
10.	To plot the transfer characteristics for n-channel MOSFET in linear region and extract the various parameters (like threshold voltage (V_{th}), Transconductance (g_m), Mobility (μ) and on-off current ratio (I_{on}/I_{off}) using MATLAB.	2

11.	To plot the transfer characteristics for n-channel MOSFET in saturation region and extract the various parameters (like threshold voltage (V_{th}), Transconductance (g_m), Mobility(μ) and on-off current ratio (I_{on}/I_{off}) using MATLAB.	2
12.	Write a program for the following condition using Xilinx. Government wants to give subsidy to the citizens, so they decided that if income is greater than subsidy then income itself is the final income. Otherwise, subsidy will be added to income to get the total income.	2
	Total	24
Innovative Experiments		
13.	FPGA implementation of various logic gates in Xilinx tool.	2
14.	Design and Simulation of universal gates in VTCAD tool.	2
15.	Design and Simulation of Tri-Gate in VTCAD tool.	2
	Total	06

11.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 191		Course Title		Advanced Nanotechnology	
2.	Contact Hours	L	3	T	0	P	0
3.	Examination Duration	Theory		3		Practical	
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	03					
6.	Semester	First					
7.	Category of Course	PE					
8.	Pre-requisite	Physics, Chemistry					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Remember the concepts of emerging world of nanoscience, Knowledge of single-electron devices and carbon based nanoelectronics devices.</p> <p>CO2: Understand the various top-down and bottom-up approaches for nanomaterial synthesis.</p> <p>CO3: Apply the acquired knowledge to develop novel nanomaterials.</p> <p>CO4: Analyze the properties of nanomaterials using various scanning probe techniques and spectroscopic techniques for material characterization.</p> <p>CO5: Evaluate the performance of nanotechnology related devices for various industrial applications.</p> <p>CO6: Utilize analytical tools in nanoscale engineering.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Introduction to Nanotechnology: Overview, Historical background, Importance of nanoscale, Bottom-up approaches, Top-down approaches, Functional approaches.	8
2.	Unit 2: Nano Materials: Fundamental concepts of nanomaterials, Allotropes of carbon, Graphene, Graphene nanoribbons, Fullerenes, Fullerites, Carbon nanotubes (CNTs), Bucky paper.	8
3.	Unit 3: Nano Electronics: Approaches to Nano electronics, Fabrication of integrated circuits, Introduction to microelectromechanical systems (MEMS), Nanoelectromechanical systems (NEMS), Nanowires, Nano-Circuits, Quantum wire, Quantum well.	10
4.	Unit 4: Nano-Engineering Devices and Nano- Medicine: Lab on chip, Micromachinery, Nanomotor, Nanopore, Nano sensor, Quantum point contact, Synthetic molecular motors, Medical applications of nanomaterials.	8
5.	Unit 5: Analytical Tools in Nanoscale Engineering and Nanolithography: Atomic force microscopy (AFM), Scanning tunnelling microscope (STM), Nanolithography: Dip-pen, Electron beam, Ion-beam sculpting, Nanoimprint lithograph, Photolithography.	10

	Total	44
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11. Suggested Books

<i>S. No.</i>	<i>Name of Authors/Books/Publishers</i>	<i>Edition</i>	<i>Year of Publication / Reprint</i>
	<i>Textbooks</i>		
1.	<i>Shunri Oda, David Ferry, "Nanoscale Silicon Devices", CRC Press, Taylor & Francis Group.</i>	<i>1st</i>	<i>2016</i>
2.	<i>Robert Puers, "Nanoelectronics: Materials, Devices, Applications", Wiley.</i>	<i>1st</i>	<i>2017</i>
	<i>Reference Books</i>		
1.	<i>Suprio Datta, "Lessons from nanoelectronics", World Scientific publisher.</i>	<i>1st</i>	<i>2012</i>
2.	<i>Gabriel M. Rebeiz, "RF MEMS: Theory, Design, and Technology", Wiley.</i>	<i>1st</i>	<i>2003</i>
3.	<i>Julian W. Gardner, "Microsensors, MEMS and Smart Devices", Wiley.</i>	<i>1st</i>	<i>2002</i>

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 192		Course Title		Optimization Techniques in VLSI Design	
2.	Contact Hours	L	3	T	0	P	0
3.	Examination Duration	Theory		3		Practical	0
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	03					
6.	Semester	First					
7.	Category of Course	PE					
8.	Pre-requisite	VLSI Technology and Design					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Recall the knowledge of modelling techniques based on incorporating empirical parameters.</p> <p>CO2: Understand the performance parameters and yield estimation of optimization techniques.</p> <p>CO3: Apply the knowledge of convex optimization techniques.</p> <p>CO4: Analyse and understand Genetic algorithm in VLSI design.</p> <p>CO5: Assess and evaluate FPGA for automatic test generation.</p> <p>CO6: Implement optimization techniques in VLSI design.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Statistical Modelling: Modelling sources of variations, Monte Carlo techniques, Process variation modelling- Pelgrom's model, Principal component-based modelling, Quad tree based modelling, Performance modelling-response Surface methodology, Delay modelling, Interconnect delay models.	8
2.	Unit 2: Statistical Performance, Power and Yield Analysis: Statistical timing analysis, Parameter space techniques, Bayesian networks leakage models, High level statistical analysis, Gate level statistical analysis, Dynamic power, Leakage power, Temperature and power supply variations, High level yield estimation and Gate level yield estimation.	8
3.	Unit 3: Convex Optimization: Convex sets, Convex functions, Geometric programming, Trade-off and sensitivity analysis, Generalized geometric programming, Geometric programming applied to digital circuit gate sizing, Floor planning, Wire sizing, Approximation and fitting- monomial fitting, Maxmonomial fitting, Posynomial fitting.	9
4.	Unit 4: Genetic Algorithm: Introduction, GA Technology-Steady state algorithm-Fitnessscaling- Inversion GA for VLSI design, Layout and test automation- Partitioning-automatic placement, Routing	9

	<i>technology, Mapping for FPGA- Automatic test generation- Partitioning algorithm taxonomy-multiway partitioning Hybrid Genetic-Encoding-Local Improvement-WDFR comparison of cas-standard cell placement-GASP algorithm-unified algorithm.</i>	
5.	Unit 5: GA Routing Procedures and Power Estimation: <i>Global routing-FPGA technology mapping-circuit Generation-Test Generation in A GA framework-test generation procedure. Power estimation-application of GA-standard cell placement-GA for ATG-problem encoding- fitness function-GA Vs conventional algorithm. Hardware/Software Co-Designs.</i>	8
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	<i>Ashish Srivastava, Dennis Sylvester, David Blaauwi, "Statistical Analysis and Optimization for VLSI: Timing and Power", Springer.</i>	1 st	2005
2.	<i>Kalyanmoy Dev, "Optimization for Engineering Design: Algorithms and Examples", PHI Learning.</i>	2 nd	2001
	Reference Books		
1.	<i>Pinaki Mazumder, E. Mrudnick, "Genetic Algorithm for VLSI Design, Layout and test Automation", Prentice Hall.</i>	1 st	2002

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	<i>Department of Electronics and Communication Engineering</i>						
1.	<i>Subject Code</i>	<i>VDM 193</i>		<i>Course Title</i>		<i>Theory and Application of Embedded Systems</i>	
2.	<i>Contact Hours</i>	<i>L</i>	<i>3</i>	<i>T</i>	<i>0</i>	<i>P</i>	<i>0</i>
3.	<i>Examination Duration</i>	<i>Theory</i>		<i>3</i>	<i>Practical</i>		<i>0</i>
4.	<i>Relative Weight</i>	<i>CIE</i>	<i>25</i>	<i>MSE</i>	<i>25</i>	<i>SEE</i>	<i>50</i>
6.	<i>Credit</i>	<i>03</i>					
6.	<i>Semester</i>	<i>First</i>					
7.	<i>Category of Course</i>	<i>PE</i>					
8.	<i>Pre-requisite</i>	<i>Microcontrollers & Embedded Systems</i>					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Recall the basic concept of embedded system.</p> <p>CO2: Understand the architecture and instruction sets of PIC microcontrollers.</p> <p>CO3: Relate the knowledge of system firmware design.</p> <p>CO4: Analyse structure of RTOS based embedded systems.</p> <p>CO5: Evaluate ARM-32 bit processors as the advanced series microcontroller.</p> <p>CO6: Integrate the concepts of advanced embedded systems for developing projects.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Embedded Systems: Embedded vs General computing system, classification, application and purpose of Embedded system. Core of an Embedded System, Memory, Sensors, Actuators. Characteristics and quality attributes of embedded systems.	8
2.	Unit 2: PIC Architectures: PIC series of microcontrollers, Assembly basics, Instruction list and description, Addressing modes, Interrupts and timer.	8
3.	Unit 3: System Firmware Design: Hardware Software Co-Design, embedded firmware design approaches, computational models, embedded firmware development languages, Integration and testing of Embedded Hardware and firmware.	8
4.	Unit 4: RTOS Based Embedded System Design: Basics of Operating systems, Types of Operating Systems, Tasks, Process and Threads, Multiprocessing and Multitasking, Task Scheduling.	8
5.	Unit 5: ARM-32 bit Microcontroller: Thumb-2 technology and applications of ARM, Architecture of ARM Cortex M3, Various Units in the architecture, General Purpose Registers, Special Registers, exceptions, interrupts, stack operation.	8
	Total	40

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	Raj Kamal, " Microcontrollers: Architecture, Programming, Interfacing and System Design ", Pearson Education India.	2 nd	2005
2.	J. Morton, " The PIC Microcontroller ", Newnes.	3 rd	2005
	Reference Books		
1.	A. Sloss, D. Symes, C. Wright, " Arm System Developer's Guide: Designing and optimizing system software ", Morgan Kauffman Publisher.	1 st	2004
2.	K. V. Shibhu, " Introduction to Embedded Systems ", Tata McGraw Hill.	1 st	2009
3.	Frank Vahid, Tony Givargis, " Embedded System Design, A Unified Hardware, Software Approach ", Wiley Publications.	3 rd	1999

12.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	Department of Electronics and Communication Engineering							
1.	Subject Code	VDM 194		Course Title		Digital Signal Processing for VLSI		
2.	Contact Hours	L	3	T	0	P	0	
3.	Examination Duration	Theory		3		Practical		0
4.	Relative Weight	CIE	25	MSE	25	SEE	50	
6.	Credit	03						
6.	Semester	First						
7.	Category of Course	PE						
8.	Pre-requisite	Digital Signal Processing						

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Recall the basic concepts of DFT- FFT in FIR filters and IIR filters.</p> <p>CO2: Understand iteration bound, pipelining and parallel processing.</p> <p>CO3: Apply the knowledge of retiming and parallel processing by using various fast convolution techniques.</p> <p>CO4: Analyse algorithmic strength reduction in filters transforms and pipelined and parallel recursive filters.</p> <p>CO5: Evaluate scaling and round off noise computation processes.</p> <p>CO6: Design and develop high-speed VLSI based devices.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Introduction: Linear system theory- Convolution- Correlation - DFT- FFT- Basic concepts in FIR filters and IIR filters- Filter realizations. Representation of DSP algorithms-block diagram-SFG-DFG.	8
2.	Unit 2: Iteration Bound: Data-Flow graph representations, Loop bound and iteration bound, Algorithms for computing iteration bound, Iteration bound of multi-rate data-flow graph. Pipelining and parallel processing: Pipelining of FIR digital filters, Parallel processing, Pipelining and parallel processing for low power.	8
3.	Unit 3: MOS Logic Circuits: Combinational MOS logic circuits: MOS logic circuit with depletion NMOS loads, CMOS logic circuits, Complex logic circuits, CMOS transmission gates. Sequential MOS logic circuits: Behaviour of bistable elements, SR latch, Clocked latch and Flip-flop, CMOS D latch and Flip-flop.	8
4.	Unit 4: Dynamic Logic Circuits: Basic principles of pass transistor circuits, Voltage bootstrapping, Synchronous dynamic circuit techniques, Dynamic CMOS circuit, High performance dynamic CMOS circuits.	9
5.	Unit 5: Low Power CMOS Logic Circuits: Overview of power consumption, Low power design through voltage scaling, Estimation and optimization of switching activity, Reduction of switched capacitance, Adiabatic logic circuits.	9

	Total	42
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11. Suggested Books

<i>S. No.</i>	<i>Name of Authors/Books/Publishers</i>	<i>Edition</i>	<i>Year of Publication / Reprint</i>
	<i>Textbooks</i>		
1.	<i>K. K. Parhi, "VLSI Digital Signal Processing", John-Wiley</i>	<i>1st</i>	<i>1999</i>
2.	<i>John G. Proakis, Dimitris G. Manolakis, "Digital Signal Processing", Prentice Hall of India.</i>	<i>3rd</i>	<i>1996</i>
	<i>Reference Books</i>		
1.	<i>Richard J. Higgins, "Digital signal processing in VLSI", Prentice Hall.</i>	<i>1st</i>	<i>1990</i>

12.	<i>Mode of Evaluation</i>	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 195		Course Title		Robust Control System	
2.	Contact Hours	L	3	T	0	P	0
3.	Examination Duration	Theory		3		Practical	
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	03					
6.	Semester	First					
7.	Category of Course	PE					
8.	Pre-requisite	Control Systems					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Explain the motivation of robust control.</p> <p>CO2: Compute nominal stability and performance along with robust stability and performance</p> <p>CO3: Explain robustness and uncertainty of systems.</p> <p>CO4: Explain robust stability and loop shaping.</p> <p>CO5: Acquire the fundamentals of H_2 and H_∞ control.</p> <p>CO6: Design feedback control systems</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Introduction and Background: Control System representations, System stabilities, Coprime factorization and stabilizing controllers, signals and systems norms.	8
2.	Unit 2: Modeling of uncertain systems: Introduction to concepts of model uncertainty, including both parametric and dynamic uncertainty, Linear fractional transformations and canonical forms.	8
3.	Unit 3: Robustness Problems: Linear fractional transformations and canonical forms. Performance measured via (induced) norms. Robust stability and performance problems. Solution of SISO robustness problems.	8
4.	Unit 4: Computer-Aided Analysis Techniques: Introduction to the structured singular value for robustness analysis of MIMO systems. Conversion of robustness problems to canonical $M-\Delta$ form. The small gain theorem and approximate computation of μ via efficient upper and lower bounds. Computer-aided tools for μ -analysis based on the Matlab Robust Control Toolbox.	10
5.	Unit 5: Synthesis and Controller: Design Optimal controller design including H_2 and H_{∞} optimal control. Scaled H_{∞} -optimal control problems and μ -synthesis. Computer-aided tools to implement D,G-K iteration for advanced controller design. Lower order controllers: Absolute error	10

	<i>approximation methods, reduction via fractional factors, relative error approximation methods, and frequency weighted approximation methods, Design case studies.</i>	
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	<i>U. Mackenroth, "Robust Control Systems-Theory and Case Studies", Springer International Edition.</i>	1 st	2003
2.	<i>Kemin Zhou, "Essentials of Robust Control", Prentice-Hall.</i>	1 st	2006
3.	Gu, Da-Wei, Petkov, Petko, Konstantinov, Mihail M , "Robust Control Design with MATLAB", Springer International Edition.	2 nd	2014
	Reference Books		
1.	<i>Richard.C.Dorf and R.T Bishop, "Modern Control System", P.H.I</i>	1 st	1994
2.	<i>S P Bhattacharya, L H Keel, H Chapellat, "Robust Control: The Parametric Approach", Prentice-Hall.</i>	2 nd	1995
3.	<i>P C Chandrasekharan, "Robust Control of Linear Dynamical Systems", Academic Press.</i>	3 rd	1996
4.	<i>R. Jacob Baker, "CMOS: circuit design, layout, and simulation", John Wiley & Sons.</i>	1 st	2002

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER I

S. No.	<i>Department of Electronics and Communication Engineering</i>						
1.	<i>Subject Code</i>	<i>VDM 196</i>		<i>Course Title</i>		<i>Control of Advanced Electric Machine</i>	
2.	<i>Contact Hours</i>	<i>L</i>	<i>3</i>	<i>T</i>	<i>0</i>	<i>P</i>	<i>0</i>
3.	<i>Examination Duration</i>	<i>Theory</i>		<i>3</i>		<i>Practical</i>	<i>0</i>
4.	<i>Relative Weight</i>	<i>CIE</i>	<i>25</i>	<i>MSE</i>	<i>25</i>	<i>SEE</i>	<i>50</i>
6.	<i>Credit</i>	<i>03</i>					
6.	<i>Semester</i>	<i>First</i>					
7.	<i>Category of Course</i>	<i>PE</i>					
8.	<i>Pre-requisite</i>	<i>Basic Electrical Engineering</i>					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Understand the principle of operation and power converter for stepper motor</p> <p>CO2: Understand the principle of operation and power converter for switched and Synchronous reluctance motor</p> <p>CO3: Understand construction, principle of operation, theory of torque production in brushless DC motor</p> <p>CO4: Explain the control aspect of special electrical machines</p> <p>CO5: Demonstrate an understanding of the fundamental control practices associated with rotating machines</p> <p>CO6: Summarize the various performance characteristics of special electrical machines.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Stepper Motors: Constructional features, principle of operation, modes of excitation, single phase stepping motors, torque production in variable Reluctance (VR) stepping motor; Dynamic characteristics, Drive systems and circuit for open loop control, Closed loop control of stepping motor, control of stepper motor using microcontroller.	10
2.	Unit 2: Switched Reluctance Motors: Constructional features, principle of operation. Torque equation, Power controllers, Characteristics and control. Microprocessor based controller. Sensor less control.	10
3.	Unit 3: Synchronous Reluctance Motors-Constructional features: Axial and radial air gap Motors. Operating principle, reluctance torque – Phasor diagram, motor characteristics.	10
4.	Unit 4: Permanent Magnet Brushless DC Motors: Commutation in DC motors, Difference between mechanical and electronic commutators, Hall sensors, Optical sensors, Multiphase Brushless motor, Square wave permanent	6

	<i>magnet brushless motor drives, Torque and EMF equation, Torque-speed characteristics, Controllers-Microprocessor based controller. Sensorless control.</i>	
5.	Unit 5: Emerging Trends and Applications: <i>Advanced control techniques, sensor less control, model predictive control, direct torque control, field-oriented control, converter control, fault diagnosis and fault-tolerant control, and emerging trends in the field.</i>	6
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	<i>Kenjo T., Sugawara A, "Stepping Motors and their Microprocessor Control", Clarendon Press, Oxford.</i>	1 st	1994
2.	<i>Miller T. J. E., "Switched Reluctance Motor and Their Control", Clarendon Press, Oxford.</i>	1 st	1993
	Reference Books		
1.	<i>Miller T. J. E., Brushless Permanent Magnet and Reluctance Motor Drives, Clarendon Press, Oxford.</i>	2 nd	1989
2.	<i>B K Bose, Modern Power Electronics & AC drives, Pearson.</i>	1 st	2002

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	<i>Department of Electronics and Communication Engineering</i>						
1.	<i>Subject Code</i>	<i>VDM 291</i>		<i>Course Title</i>		<i>Micro-Sensors and MEMS</i>	
2.	<i>Contact Hours</i>	<i>L</i>	<i>3</i>	<i>T</i>	<i>0</i>	<i>P</i>	<i>0</i>
3.	<i>Examination Duration</i>	<i>Theory</i>		<i>3</i>		<i>Practical</i>	
4.	<i>Relative Weight</i>	<i>CIE</i>	<i>25</i>	<i>MSE</i>	<i>25</i>	<i>SEE</i>	<i>50</i>
6.	<i>Credit</i>	<i>03</i>					
6.	<i>Semester</i>	<i>Second</i>					
7.	<i>Category of Course</i>	<i>PE</i>					
8.	<i>Pre-requisite</i>	<i>VLSI Technology</i>					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Recall the basic principles of different sensors and actuators</p> <p>CO2: Understand the process of miniaturization of a sensor and actuator to produce a micro sensor and micro actuator and its integration with microelectronics circuitry.</p> <p>CO3: Apply various fabrication technologies for miniaturization of sensors and actuators for MEMS.</p> <p>CO4: Analyze the different properties of sensors and actuators.</p> <p>CO5: Evaluate the behavior of MEMS devices.</p> <p>CO6: Create approaches for the designing of different MEMS based devices for various real-life applications.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Microfabrication and Micromachining: <i>Integrated circuit processes, Bulk micromachining, Isotropic etching and anisotropic etching, Wafer bonding, High aspect-ratio processes (LIGA).</i>	10
2.	Unit 2: Physical Micro-Sensors: <i>Classification of physical sensors, Integrated, Intelligent, Smart sensors, Sensor principles and examples: Thermal sensors, Electrical sensors, Mechanical sensors, Chemical and biosensors.</i>	8
3.	Unit 3: Micro actuators: <i>Electromagnetic and thermal micro-actuation, Mechanical design of micro actuators, Micro actuator examples, Microvalves, Micropumps, Micromotors Micro actuator systems, Success stories, Ink-Jet printer heads, Micro-Mirror TV projector.</i>	8
4.	Unit 4: Surface Micromachining: <i>One or two sacrificial layer processes, Surface micromachining requirements, Polysilicon surface micromachining, Other compatible materials, Silicon dioxide, Silicon nitride, Piezoelectric materials, Surface micromachined systems: Success stories, Micromotors, Gear trains mechanisms.</i>	8
5.	Unit 5: Application Areas:	8

	<i>All-mechanical miniature devices, 3-D electromagnetic actuators and sensors, RF/Electronics devices, Optical/Photonic devices, Medical devices E.G. DNA-chip, Micro-arrays. MEMS for RF applications: Need for RF MEMS components in communications, Space and defence applications</i>	
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	Chang Liu, " Foundations of MEMS ", Pearson.	2 nd	2012
2.	Rai - Choudhury P., " MEMS and MOEMS Technology and Applications ", PHI Learning Private Limited.	1 st	2009
3.	Julian W. Gardner, " Microsensors, MEMS and Smart Devices ", Wiley.	1 st	2002
	Reference Books		
1.	Gabriel M. Rebeiz, " RF MEMS: Theory, Design, and Technology ", Wiley.	1 st	2003
2.	Stephen D. Senturia, " Microsystem design ", Springer.	1 st	2006

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	<i>Department of Electronics and Communication Engineering</i>						
1.	<i>Subject Code</i>	<i>VDM 292</i>		<i>Course Title</i>		<i>RF Microelectronics Devices</i>	
2.	<i>Contact Hours</i>	<i>L</i>	<i>3</i>	<i>T</i>	<i>0</i>	<i>P</i>	<i>0</i>
3.	<i>Examination Duration</i>	<i>Theory</i>		<i>3</i>		<i>Practical</i>	
4.	<i>Relative Weight</i>	<i>CIE</i>	<i>25</i>	<i>MSE</i>	<i>25</i>	<i>SEE</i>	<i>50</i>
6.	<i>Credit</i>	<i>03</i>					
6.	<i>Semester</i>	<i>Second</i>					
7.	<i>Category of Course</i>	<i>PE</i>					
8.	<i>Pre-requisite</i>	<i>Electronics Devices and Circuits, Microwave Engineering</i>					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Recall the concepts of wireless technology in RF design</p> <p>CO2: Understand the modulation techniques for RF circuits.</p> <p>CO3: Apply the basics of detectors and transistor modelling, Mobile RF communication systems and basics of multiple access techniques.</p> <p>CO4: Analyse the concept of BJT and MOSFET behaviour at RF frequencies.</p> <p>CO5: Assess and evaluate Radio frequency devices.</p> <p>CO6: Design and develop RF based microelectronic devices.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Introduction: <i>Introduction to RF and wireless technology: Complexity, Design and applications, Choice of technology. Basic concepts in RF design, Nonlinearly and time variance, Random processes and noise.</i>	8
2.	Unit 2: Modulation Techniques for RF Circuits: <i>Definition of sensitivity, Dynamic range, Conversion gains and distortion. Analog and Digital modulation for RF circuits: Comparison of various techniques for power efficiency. Coherent and non-coherent detection.</i>	10
3.	Unit 3: Detectors and Transistor Modelling: <i>Mobile RF communication systems and basics of multiple access techniques. Receiver and transmitter architectures and testing heterodyne, Homodyne, Image-reject, Direct-IF and sub-sampled receivers. Direct conversion and two steps transmitters. BJT and MOSFET behaviour at RF frequencies, Modelling of the transistors and SPICE models.</i>	8
4.	Unit 4: Mixers and Oscillators: <i>Noise performance and limitation of devices. Integrated parasitic elements at high frequencies and their monolithic implementation. Basic blocks in RF systems and their VLSI implementation: Low noise amplifiers design in various technologies, Design of mixers at GHz frequency range. Various mixers, Their working and implementations, Oscillators: Basic topologies VCO and definition of phase noise. Noise-power trade-off. Resonator less VCO design. Quadrature and single-sideband generators.</i>	8

5.	Unit 5: RF Synthesizer: Radio frequency synthesizers: PLLS, Various RF synthesizer architectures and frequency dividers, Power amplifiers design. Linearization techniques, Design issues in integrated RF filters. Some discussion on available CAD tools for RF VLSI designs.	8
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	B. Razavi, "RF Microelectronics", Prentice-Hall PTR.	2 nd	2012
2.	T. H. Lee, "The Design of CMOS Radio-Frequency Integrated Circuits", Cambridge University Press.	1 st	1998
	Reference Books		
1.	R. Jacob Baker, H. W. Li, and D.E. Boyce, "CMOS circuit design, Layout and simulation", Prentice-Hall of India.	1 st	1998

12.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 293		Course Title		VLSI Circuits for Biomedical Application	
2.	Contact Hours	L	3	T	0	P	0
3.	Examination Duration	Theory		3		Practical	
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	03					
6.	Semester	Second					
7.	Category of Course	PE					
8.	Pre-requisite	Advanced VLSI Circuit Design, CMOS Analog Circuit Design					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Recall the concepts of neurochemical and neuro potential devices.</p> <p>CO2: Understand the mechanisms involved in the design of CMOS circuits for implantable biomedical devices and wireless biomedical applications.</p> <p>CO3: Analyze CMOS circuits for wireless medical application.</p> <p>CO4: Apply microneedles and their interfacing with neural systems.</p> <p>CO5: Evaluate the process of neuro-signal acquisition and amplification, neurochemical signal recording, and neuro stimulation.</p> <p>CO6: Develop CMOS circuits for biomedical applications.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Introduction: Wireless integrated neurochemical and neuropotential circuits: Introduction, Neurochemical sensing, Neuropotential sensing, RF telemetry and power harvesting in implanted devices, Multimodal electrical and chemical sensing. Visual cortical neuroprosthesis: A system approach: Introduction, System architecture, Prosthesis exterior body unit and wireless link, Body implantable unit, System prototype.	9
2.	Unit 2: CMOS Circuits for Biomedical Implantable Devices: Introduction, Inductive link to deliver power to implants, High data rate transmission through inductive links, Energy and bandwidth issues in multi-channel bio-potential recording. Towards self-powered sensors and circuits for biomedical implants: Introduction, Stress, Strain and fatigue predication, In vivo strain measurement and motivation. Fundamental of piezoelectric-transduction and power delivery, Sub-microwatt piezo-powered VLSI circuits.	9
3.	Unit 3: CMOS Circuits for Wireless Medical Application: Introduction, Spectrum regulations for medical use, Integrated receiver and transmitter architecture, Radio architecture, System budget, Low noise amplifier, Mixer, Polyphase filter, Power amplifier, PLL. Error correcting codes for in vivo RF wireless links.	8

4.	Unit 4: Microneedles: <i>Introduction, Fabrication methods for hollow-out-of-plane microneedles, Application for microneedles. Integrated circuit for neural interfacing: Introduction, nature of neural signals, Neural signal amplification.</i>	8
5.	Unit 5: Integrated Circuits for Neural Applications: <i>Integrated circuit for neural interfacing (Neurochemical recording), Integrated circuit for neural interfacing (Neural Stimulation): Introduction, Electrode configuration and tissue volume conductor, Electrode- Electrolyte Interface, Efficacy, Stimulus generator, Stimulation front end circuits.</i>	8
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	Kris Iniewski, " VLSI Circuit Design for Biomedical Application ", Artech House Publishers,	1 st	2008
2.	D. A. Hodges, H. G. Jackson and R. A. Saleh, " Analysis and Design of Digital Integrated Circuits in Deep Submicron Technology ", Tata McGraw-Hill,	3 rd	2003
	Reference Books		
1.	Parag. K. Lala, " Digital circuit testing and testability ", Academic Press.	1 st	1997
2.	Ashok K. Sharma, " Semiconductor memories technology, testing and reliability ", Prentice-Hall of India Private Limited.	1 st	2002

12.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	<i>Department of Electronics and Communication Engineering</i>							
1.	<i>Subject Code</i>	<i>VDM 294</i>		<i>Course Title</i>		<i>Microwave & MM-wave Integrated Circuits and Applications</i>		
2.	<i>Contact Hours</i>	<i>L</i>	3	<i>T</i>	0	<i>P</i>	0	
3.	<i>Examination Duration</i>	<i>Theory</i>		3		<i>Practical</i>		0
4.	<i>Relative Weight</i>	<i>CIE</i>	25	<i>MSE</i>	25	<i>SEE</i>	50	
6.	<i>Credit</i>	03						
6.	<i>Semester</i>	Second						
7.	<i>Category of Course</i>	PE						
8.	<i>Pre-requisite</i>	<i>Microwave Engineering</i>						

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Describe the requirement of MMIC and MM-wave technologies and their various applications.</p> <p>CO2: Understand the fabrication processes Circuit of Microwave Integrated MIC.</p> <p>CO3: Implement the various active and passive circuit elements for microwave and MM-wave technology.</p> <p>CO4: Analyze the various measurement systems using MM-wave technology.</p> <p>CO5: Evaluate the microwave components for designing microwave Integrated circuits.</p> <p>CO6: Design of MMIC using MM-Wave Technology.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Introduction: Introduction to Monolithic Microwave Integrated Circuits (MMICs) technology, different types of MMIC, Advantages disadvantages and application of MMICs, MMIC fabrication techniques, Thick and thin film technologies and materials, Encapsulation and mounting of active devices, Introduction to MM-wave integrated circuits, GaAs fabrication technology and various processes, Materials used for MM-wave integrated guides.	10
2.	Unit 2: Passive components: Introduction, Inductors, Capacitors, Resistors, Via-holes, and grounding, Microstrip components, Coplanar circuits, Multilayer techniques, Micromachined passive components.	8
3.	Unit 3: Active Semiconductor circuit elements: Active device technologies and design approaches, Fabrication and modeling: Bipolar junction transistor, Hetero junction bipolar transistor, High electron mobility transistor, MESFET, CMOS, BiCMOS.	10

4.	Unit 4: Measurement Techniques: <i>Introduction, Test fixture measurements, Probe station measurements, Thermal and cryogenic measurements, Experimental field probing techniques, MM-wave measurement techniques: Electric field probe, Measurement of attenuation constant and guide wavelength. Measurement at radiation loss at bends.</i>	8
5.	Unit 5: System Application: <i>MICs in phased array radars, MICs in satellite television systems, Microwave radio systems, Monolithic MM-wave transceiver.</i>	6
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	<i>I. D. Robertson and S. Lucyszyn, "RFIC and MMIC design and technology", The Institute of Electrical Engineers.</i>	2 nd	2001
2.	<i>Leo G. Maloratsk, "Passive RF and Microwave Integrated Circuits", Elsevier.</i>	1 st	2004
3.	<i>K. C. Gupta and A. Singh, "Microwave Integrated circuit", John Wiley & Sons.</i>	2 nd	1974
4.	<i>E. Carey and S. Lidholm, "Millimeter wave Integrated Circuit", Springer.</i>	2 nd	2005
	Reference Books		
1.	<i>I. Kneppo, J. Fabian, P. Bezousek, P. Hrnicko and M. Pavel, "Microwave Integrated Circuits".</i>	1 st	1994
2.	<i>S. K. Koul, "Millimeter Wave and Optical Dielectric Integrated Guides and Circuits", John Wiley & Sons.</i>	1 st	1997
3.	<i>Duixian Liu, Ulrich Pfeiffer, Janusz Grzyb and Brian Gaucher, "Advanced Millimeter-wave Technologies: Antennas, Packaging and Circuits", Wiley.</i>	1 st	2009

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	<i>Department of Electronics and Communication Engineering</i>						
1.	<i>Subject Code</i>	<i>VDM 295</i>		<i>Course Title</i>		<i>Renewable Energy Resources and Energy Management</i>	
2.	<i>Contact Hours</i>	<i>L</i>	3	<i>T</i>	0	<i>P</i>	0
3.	<i>Examination Duration</i>	<i>Theory</i>		3		<i>Practical</i>	0
4.	<i>Relative Weight</i>	<i>CIE</i>	25	<i>MSE</i>	25	<i>SEE</i>	50
6.	<i>Credit</i>	03					
6.	<i>Semester</i>	<i>Second</i>					
7.	<i>Category of Course</i>	<i>PE</i>					
8.	<i>Pre-requisite</i>	<i>Physics</i>					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Describe the knowledge of Solar Power Generation and solar thermal applications.</p> <p>CO2: Illustrate the photovoltaic characteristics, classifications, fuel cells and wind energy systems.</p> <p>CO3: Demonstrate the Geothermal energy for conversion in electrical energy.</p> <p>CO4: Analyse the performance analysis of Fuel cell and MHD.</p> <p>CO5: Evaluate the various renewable power generation techniques and: compare the results.</p> <p>CO6: Develop solar panels, fuel cells and wind energy techniques.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Solar Thermal Energy: Solar radiation flat plant collectors and their materials, application and performance, focusing of collectors and their materials, applications and performance solar thermal power plants, thermal energy storage for solar heating and cooling, limitations .	10
2.	Unit 2: Photo voltaic System Solar cell characteristics, solar cell classifications, solar cell module, panel and Array constructions, Maximizing solar PV output and Load Matching, Maximum Power Point Tracking (MPPT), Balance of system components, Solar PV applications	10
3.	Unit 3: Fuel Cells: Principle of working of various types of fuel cells and their working, performance and limitations. Thermo-electrical and thermionic Conversions: Principle of working, performance and limitations	10
4.	Unit 4: Wind Energy: Wind power and its sources, site selection, criterion , momentum theory, classification of rotors , concentrations and augments, wind characteristics . performance and limitations of energy conversion systems.	6

5.	<p>Unit 5: Geothermal Energy: Resources of geothermal energy, thermodynamics of geo-thermal energy conversion- electrical conversion, non-electrical conversion, environmental considerations. Magneto-hydrodynamics (M H D): Principle of working of M H D Power plant, performance and limitations. Bio-mass: Availability of bio-mass and its convention theory.</p>	6
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	B.H Khan, " Non-Conventional Energy Resources " Tata McGraw-Hill Education.	2 nd	2000
2.	Max Kurtz , " Handbook of Engineering Economics: Guide for Engineers, Technicians, Scientists, and Managers ", McGraw-Hill.	1 st	1984
3.	A. Mani, " Handbook of solar radiation Data for India . " Allied Publishers Pvt. Ltd.	1 st	1980
4.	Peter Auer , " Advances in Energy System and Technology ", Vol. I & II Edited by Academic Press.	1 st	1999
5.	F.R. the MITTRE , " Wind Machines " by Energy Resources and Environmental Series". Van Nostrand Reinhold Inc.,U.S.	2 nd	1980
	Reference Books		
1.	Frank Kreith , " Solar Energy Hand Book ", Springer.	1 st	1994
2.	Chermisinogg and Thomes , C. Reign , " Principles and Application of solar Energy ". TMH.	2 nd	1980

12.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER II

S. No.	<i>Department of Electronics and Communication Engineering</i>						
1.	<i>Subject Code</i>	<i>VDM 296</i>		<i>Course Title</i>		<i>Multivariable Control Systems</i>	
2.	<i>Contact Hours</i>	<i>L</i>	<i>3</i>	<i>T</i>	<i>0</i>	<i>P</i>	<i>0</i>
3.	<i>Examination Duration</i>	<i>Theory</i>		<i>3</i>		<i>Practical</i>	
4.	<i>Relative Weight</i>	<i>CIE</i>	<i>25</i>	<i>MSE</i>	<i>25</i>	<i>SEE</i>	<i>50</i>
6.	<i>Credit</i>	<i>03</i>					
6.	<i>Semester</i>	<i>Second</i>					
7.	<i>Category of Course</i>	<i>PE</i>					
8.	<i>Pre-requisite</i>	<i>Basic Electrical Engineering</i>					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Recall the used of classical control in multivariable systems</p> <p>CO2: Extend the basic knowledge and understanding of the multivariable systems</p> <p>CO3: Implement the multivariable systems through open and closed loop transfer function and study of their behaviour.</p> <p>CO4: Analyze a multivariable dynamic system</p> <p>CO5: Evaluate the stability, performance and robustness of a closed-loop system</p> <p>CO6: Design an appropriate controller for the multivariable system</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Introduction to Multi-variable systems: Classical feedback control in the multivariable case, Introduction to multivariable control, Elements of linear systems theory, Limitations on performance in SISO and MIMO systems.	8
2.	Unit 2: Analysis of Multi-Variable System: Open loop dynamic analysis in state space, Multi-variable transfer function, Multi variable pole – zero concept, quantitative measure of singularity, closed loop dynamic analysis.	10
3.	Unit 3: Multi – Single loop designs: Preliminary consideration of interaction analysis and loop pairing, the relative gain array, loop pairing using RGA, loop pairing of nonlinear system, loop pairing for system with pure integrator modes, loop pairing for non-square systems, multi-loop controller, controller tuning for multi-loop system.	8
4.	Unit 4: Introduction to De-couplers: Introduction, Decoupling, feasibility of steady state de-coupler design, steady state decoupling by singular value decomposition.	8
5.	Unit 5: Design of multivariable systems:	8

	<i>Multi-loop controller Design procedure, Controller tuning for multi-loop system, Multivariable controller design.</i>	
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	<i>Y. S. Apte, Linear multivariable control system, Tata McGraw Hill.</i>	1 st	1981
2.	<i>Dale E. Seborg, Thomas F. Edgar, and Duncan A. Mellichamp, Process Dynamics and Control, Wiley India</i>	1 st	2003
	Reference Books		
1.	<i>C. T. Chen, Linear system theory and design, Oxford University Press, 1999.</i>	1 st	1999
2.	<i>John Bay, Fundamentals of linear state space systems, Tata McGraw Hill, 1998.</i>	1 st	1998
3.	<i>Wilson Rugh, Linear system theory, Prentice Hall, 1996.</i>	1 st	1996

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER III

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 391		Course Title		Organic Electronics Devices and Circuits	
2.	Contact Hours	L	3	T	0	P	0
3.	Examination Duration	Theory		3		Practical	
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	03					
6.	Semester	Third					
7.	Category of Course	PE					
8.	Pre-requisite	Basic Electronics Engineering, Electronics Devices and Circuits.					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Ability to describe basic concepts and limitations of conventional silicon-based semiconductor devices.</p> <p>CO2: Understand the basic concepts and classification of organic materials.</p> <p>CO3: Apply the advancement of charge transport in organic materials for different organic electronic devices.</p> <p>CO4: Design and develop innovative organic electronic devices.</p> <p>CO5: Evaluate the performance of organic solar cells.</p> <p>CO6: Analyse the different properties of OLED.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Organic Materials and Device Physics: Introduction; Organic materials: Conducting polymers and small molecules, Organic semiconductors: p-type and n-type semiconductors, Source, Drain and Gate electrodes, Gate dielectrics, Substrate. Energy band diagram and concept of charge transport in organic semiconductors; Comparison between organic and inorganic semiconductors including the merits, Demerits and limitations.	10
2.	Unit 2: Organic Thin Film Transistors (OTFTs): Introduction; Operating principle; Output and transfer characteristics; Classification of various organic thin film transistors (OTFT) structures; Performance parameters; Impact of structural parameters on behaviour of OTFT; Concept of contact resistance; Single Gate (SG) and Dual Gate (DG) TFT performance comparison; Merits, Demerits, Limitations and future scope. Applications: - Organic complementary inverter circuits; Organic memory - Organic static random-access memory (OSRAM).	8
3.	Unit 3: Organic Light Emitting Diodes (OLEDs) Introduction; Organic materials for OLEDs; Classification of OLEDs, Operating principle; Output and transfer characteristics; Analysis of OLED performance: Optical, Electrical and thermal properties, Merits and demerits; Stability issues; OLEDs as display applications.	8

4.	Unit 4: Organic Solar Cell: <i>Introduction; Operating principle; Characteristics; Materials for organic solar cells; Classification of organic solar cell- Single layer, Bi-layer and bulk hetero junction organic solar cell; Merits and demerits; Applications and future scope.</i>	8
5.	Unit 5: Organic Sensors: <i>Introduction; Working principle and organic sensing materials for pressure sensors (Piezoresistive, Piezoelectric, and Capacitive sensor), Temperature sensors, Humidity sensors and pH sensor; comparison between organic and conventional sensors including merits, demerits and limitations; Applications of organic sensors; Basics of ionic polymer-metal composites (IPMC) and its applications.</i>	8
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	Hagen Klauk, " Organic Electronics: Materials, Manufacturing and Applications ", Wiley-VCH VerlagGmbH & Co. KGaA, Germany, 1 st Edition, 2006.	1 st	2006
2.	Klaus Mullen, Ullrich Scherf, " Organic Light Emitting Devices: Synthesis, Properties and Applications ", Wiley-VCH VerlagGmbH & Co. KGaA, Germany, 1 st Edition, 2005.	1 st	2002
3.	Johannes Karl Fink, " Polymeric Sensors and Actuators ", John Wiley & Sons, 1 st Edition, 2012.	1 st	2012
	Reference Books		
1.	Hagen Klauk, " Organic Electronics II: More Materials and Applications ", Wiley-VCH VerlagGmbH & Co. KGaA, Weinheim, Germany.	1 st	2012
2.	Flora Li, Arokia Nathan, Yiliang Wu, Beng S. Ong, " Organic Thin Film Transistor Integration: A Hybrid Approach ", Wiley-VCH, Germany.	1 st	2011
3.	Wolfgang Brütting, " Physics of Organic Semiconductors ", Wiley-VCH VerlagGmbH & Co. KGaA, Germany.	2 nd	2005
4.	Daniel A. Bernards, Róisín M. Owens, George G. Malliaras, " Organic Semiconductors in Sensor Applications ", Springer Science & Business Media.	1 st	2008

12.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER III

S. No.	<i>Department of Electronics and Communication Engineering</i>						
1.	<i>Subject Code</i>	<i>VDM 392</i>		<i>Course Title</i>		<i>Memory Design and Testing</i>	
2.	<i>Contact Hours</i>	<i>L</i>	<i>3</i>	<i>T</i>	<i>0</i>	<i>P</i>	<i>0</i>
3.	<i>Examination Duration</i>	<i>Theory</i>		<i>3</i>	<i>Practical</i>		<i>0</i>
4.	<i>Relative Weight</i>	<i>CIE</i>	<i>25</i>	<i>MSE</i>	<i>25</i>	<i>SEE</i>	<i>50</i>
6.	<i>Credit</i>	<i>03</i>					
6.	<i>Semester</i>	<i>Third</i>					
7.	<i>Category of Course</i>	<i>PE</i>					
8.	<i>Pre-requisite</i>	<i>Low Power VLSI Design</i>					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Acquire the fundamental knowledge of CMOS memory devices.</p> <p>CO2: Infer about configuration of fundamental VLSI chip.</p> <p>CO3: Ability to implement high performance digital VLSI memory systems.</p> <p>CO4: Analyze different techniques required to implement low power memory chip.</p> <p>CO5: Evaluate the characteristics digital VLSI memory systems.</p> <p>CO6: Design of low power memory devices.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	<p>Unit 1: Introduction to Memory Chip Design: Basics of Semiconductor Memory, Internal Organization of Memory Chips, Memory Cell Array, Peripheral Circuit, I/O Interface Categories of Memory Chip, History of Memory-Cell Development, Architectures of memory cell: SRAM Cell, DRAM Cell Trends in Non-Volatile Memory Design and Technology, Ferroelectric memory, Basic Operation of Flash Memory Cells, Advances in Flash-Memory Design and Technology.</p>	10
2.	<p>Unit 2: Basics of RAM Design and Technology: Devices, NMOS Static Circuits, NMOS Dynamic Circuits, CMOS Circuits, Basic Memory Circuits, Scaling Law. On-Chip Voltage Generators: Substrate-Bias Voltage (VBB) Generator, Voltage Up Converter, Voltage Down-Converter, Half-VDD Generator, Examples of Advanced On-Chip Voltage Generators.</p>	8
3.	<p>Unit 3: DRAM Circuits: High-Density Technology, High-Performance Circuits, Catalog Specifications of the Standard DRAM, Basic Configuration and Operation of the DRAM Chip, Chip Configuration, Address Multiplexing, Fundamental Chip, Multi-divided Data Line and Word Line, Read and Relevant Circuits, Write and Relevant Circuits, Refresh-Relevant Circuits, Redundancy Techniques, On-Chip Testing Circuits, High Signal-to-Noise Ratio</p>	8

	<i>DRAM Design and Technology, Trends in High S/N Ratio Design, Data-Line Noise Reduction, Noise Sources.</i>	
4.	Unit 4: High-Performance Subsystem Memories: <i>Hierarchical Memory Systems, Memory-Subsystem Technologies, High-Performance Standard DRAMs, Embedded Memories. Low-Power Memory Circuits: Sources and Reduction of Power Dissipation in a RAM Subsystem and Chip, Low-Power DRAM Circuits, Low-Power SRAM Circuits.</i>	8
5.	Unit 5: Ultra-Low-Voltage Memory Circuits: <i>Design Issues for Ultra-Low-Voltage RAM Circuits, Reduction of the Subthreshold Current, Stable Memory-Cell Operation, Suppression of, or Compensation for, Design Parameter Variations, Power-Supply Standardization, Ultra-Low Voltage DRAM Circuits, Ultra-Low-Voltage SRAM Circuits, Ultra-Low-Voltage SOI Circuits.</i>	8
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	<i>Itoh, K., VLSI Memory Chip Design, Springer,</i>	3rd	2006
2.	<i>Sharma, A. K., Semiconductor Memories: Technology, Testing and Reliability, Wiley- IEEE press, 1st Edition, 2002.</i>	1 st	2002
	Reference Books		
1.	<i>J. B. Kuo and J. H. Lou, Low "Voltage CMOS VLSI Circuits", Wiley.</i>	1 st	1999
2.	<i>J. M. Rabaey, A. P. Chandrakasan and B. Nikolic, "Digital Integrated Circuits: A Design Perspective".</i>	2 nd	2003

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER III

S. No.	<i>Department of Electronics and Communication Engineering</i>							
1.	<i>Subject Code</i>	<i>VDM 393</i>		<i>Course Title</i>		<i>System on Chip Design and Testing</i>		
2.	<i>Contact Hours</i>	<i>L</i>	3	<i>T</i>	0	<i>P</i>	0	
3.	<i>Examination Duration</i>	<i>Theory</i>		3		<i>Practical</i>		0
4.	<i>Relative Weight</i>	<i>CIE</i>	25	<i>MSE</i>	25	<i>SEE</i>	50	
6.	<i>Credit</i>	03						
6.	<i>Semester</i>	Third						
7.	<i>Category of Course</i>	PE						
8.	<i>Pre-requisite</i>	VLSI Technology						

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Recall the concepts of System-On-Chip (SoC) Testing.</p> <p>CO2: Understand the concepts of digital test architectures design.</p> <p>CO3: Apply the concepts of SoC on delay testing and low-power testing.</p> <p>CO4: Analyze the basics of system/network-on-chip test architectures.</p> <p>CO5: Assess and evaluate debug and diagnosis.</p> <p>CO6: Implement different testing techniques in SoC.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	<p>Unit 1: Introduction: Importance of system-on-chip testing, Basics of SoC testing, Basics of memory testing, SoC design examples.</p> <p>Digital Test Architectures: Scan design, Logic built-In self-test, Test compression, Random-access scan design.</p> <p>Fault-Tolerant Design: Fundamentals of fault tolerance, Fundamentals of coding theory, Fault tolerance schemes</p>	8
2.	<p>Unit 2: System/Network-on-Chip Test Architectures: System-on-Chip (SoC) testing, Network-on-Chip (NoC) testing, Design and test practice: Case studies.</p> <p>SIP Test Architectures: Introduction, Bare die, Functional system test, Test of embedded components.</p> <p>Delay Testing: Delay test application, Delay fault models, Delay test sensitization, Delay fault, Delay fault test generation, Pseudo-functional testing to avoid over-testing</p>	8
3.	<p>Unit 3: Low-Power Testing: Introduction, Energy and power modelling, Test power issues, Low-power scan testing, Low-power built-in self-test, Low-power test data compression, Low-power RAM testing.</p> <p>Coping with Physical Failures, Soft Errors, and Reliability Issues: Signal integrity, Manufacturing defects, Process variations, and Reliability, Soft errors, Defect and error tolerance.</p>	8

4.	<p>Unit 4: Design for Manufacturability and Yield: Introduction, Yield, components of yield, Photolithography, DFM and DFY, Variability, Metrics for DFX.</p> <p>Design for Debug and Diagnosis: Introduction to logic design for debug and diagnosis (DFD) structures, Probing technologies, Circuit editing, Physical DFD structures, Diagnosis and debug process.</p>	8
5.	<p>Unit 5: Software-Based Self-Testing: Introduction, Software-based self-testing paradigm, Processor functional fault self-testing, Processor structural fault self-testing, Processor self-diagnosis, testing global interconnect, testing nonprogrammable cores, Instruction-level DFT, DSP-Based Analog/Mixed-signal component testing.</p> <p>Field Programmable Gate Array Testing: Overview of FPGAs, Testing approaches, BIST of programmable resources, Embedded processor-based testing</p>	10
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	Laung-Terng Wang, Charles E. Stroud, Nur A. Touba, “ System-On-Chip Test Architectures (Nanometer Design for Testability) ”.	1 st	2008
	Reference Books		
1.	Erik Larsson, “ Introduction to Advanced system- on- chip test design and optimization ”, Springer.	5 th	2006

12.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER III

S. No.	<i>Department of Electronics and Communication Engineering</i>						
1.	<i>Subject Code</i>	<i>VDM 394</i>		<i>Course Title</i>		<i>VLSI Physical Design Automation</i>	
2.	<i>Contact Hours</i>	<i>L</i>	3	<i>T</i>	0	<i>P</i>	0
3.	<i>Examination Duration</i>	<i>Theory</i>		3		<i>Practical</i>	0
4.	<i>Relative Weight</i>	<i>CIE</i>	25	<i>MSE</i>	25	<i>SEE</i>	50
6.	<i>Credit</i>	03					
6.	<i>Semester</i>	Third					
7.	<i>Category of Course</i>	PE					
8.	<i>Pre-requisite</i>	<i>Basic Electronics Engineering, Digital Electronics.</i>					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Recall the concepts of VLSI design automation tools.</p> <p>CO2: Understand different layout compaction, placement, and routing algorithms.</p> <p>CO3: Apply the concepts of Logic Synthesis in VLSI design.</p> <p>CO4: Analyze floor planning and routing algorithms.</p> <p>CO5: Assess and evaluate scheduling algorithms, allocation, and assignment.</p> <p>CO6: Optimize design layouts for floor-planning, placement, and routing..</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: VLSI Design Automation Tools: <i>Design cycle, Design styles, Algorithms and system design, Structural and logic design, Transistor level design, Layout design, Verification methods, Design management tools.</i>	10
2.	Unit 2: Layout Compaction, Placement and Routing: <i>Design rules, Symbolic layout, Applications of compaction, Formulation methods, Algorithms for constrained graph compaction, Circuit representation, Wire length estimation, Placement algorithms, Partitioning algorithms.</i>	8
3.	Unit 3: Floor Planning and Routing: <i>Floor planning concepts, Shape functions and Floor planning, Sizing, Local routing, Area routing, Channel routing, Global routing and its algorithms.</i>	8
4.	Unit 4: Simulation and Logic Synthesis: <i>Gate level and switch level modelling and simulation. Introduction to combinational logic synthesis, ROBDD principles, Implementation, Construction and manipulation, Logic synthesis.</i>	8
5.	Unit 5: High-Level Synthesis: <i>Hardware model for high level synthesis, Internal representation of input algorithms, Allocation, Assignment and scheduling, Scheduling algorithms. Aspects of assignment.</i>	8
	Total	42

11. Suggested Books

<i>S. No.</i>	<i>Name of Authors/Books/Publishers</i>	<i>Edition</i>	<i>Year of Publication / Reprint</i>
	<i>Textbooks</i>		
1.	<i>S. H. Gerez, "Algorithms for VLSI Design Automation", John Wiley.</i>	3 rd	2000
2.	<i>N. A. Sherwani, "Algorithms for VLSI Physical Design Automation", Kluwer.</i>	3 rd	1999
	<i>Reference Books</i>		
1.	<i>M. Sait, H. Youssef, "VLSI Physical Design Automation", World scientific.</i>	1 st	1999
2.	<i>M. Sarrafzadeh, "Introduction to VLSI Physical Design", McGraw Hill (IE).</i>	1 st	1996

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER III

S. No.	<i>Department of Electronics and Communication Engineering</i>						
1.	<i>Subject Code</i>	<i>VDM 395</i>		<i>Course Title</i>		<i>Power Quality Assessment</i>	
2.	<i>Contact Hours</i>	<i>L</i>	<i>3</i>	<i>T</i>	<i>0</i>	<i>P</i>	<i>0</i>
3.	<i>Examination Duration</i>	<i>Theory</i>		<i>3</i>		<i>Practical</i>	<i>0</i>
4.	<i>Relative Weight</i>	<i>CIE</i>	<i>25</i>	<i>MSE</i>	<i>25</i>	<i>SEE</i>	<i>50</i>
6.	<i>Credit</i>	<i>03</i>					
6.	<i>Semester</i>	<i>Third</i>					
7.	<i>Category of Course</i>	<i>PE</i>					
8.	<i>Pre-requisite</i>	<i>Basic Electrical Engineering</i>					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Describe the characteristics of ac transmission system, shunt and series reactive compensation.</p> <p>CO2: Understand waveform distortion and processing techniques, and their power assessment concepts.</p> <p>CO3: Demonstrate the working principles of FACTS devices and their operating characteristics.</p> <p>CO4: Analyze Static Synchronous Compensator (STATCOM).</p> <p>CO5: Estimate the working principles of devices to improve power quality.</p> <p>CO6: Propose the power quality monitoring system and their harmonic analysis.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	Unit 1: Introduction: <i>Power quality-voltage quality-overview of power quality phenomena-classification of power quality issues-power quality measures and standards-THD-TIF-DIN-message weights-flicker factor-transient phenomena-occurrence of power quality problems-power acceptability curves-IEEE guides, EMC standards and recommended practices.</i>	8
2.	Unit 2: Power Assessment under Waveform Distortion & Processing Techniques: <i>Introduction, single phase definitions, three phase definitions, illustrative examples, Fundamental frequency characterization, Fourier analysis, Fast Fourier Transform, Window functions, Efficiency of FFT algorithms, alternative transforms, wavelet transform, Hartely transform, Automation of disturbance recognition.</i>	8
3.	Unit 3: Power Quality Monitoring: <i>Introduction, transducers, CT, PT, power quality instrumentation, Harmonic monitoring, event recording, flicker monitoring, assessment of voltage and current unbalance, examples of application</i>	6
4.	Unit 4: Evaluation of power system harmonic distortion: <i>Introduction, direct harmonic analysis, incorporation of harmonic voltage sources, derivation of network harmonic impedances, solution by direct injection, Representation</i>	6

	<i>of individual power system components, implementation of harmonic analysis, post processing and display of results.</i>	
5.	Unit 5: Harmonic Mitigation & Grounding: <i>Passive filtering, Harmonic resonance, Impedance Scan Analysis-Active Power Factor Corrected Single Phase Front End, introduction to three Phase APFC and Control Techniques, Grounding and wiring-introduction-NEC grounding requirements-reasons for grounding-typical grounding and wiring problems-solutions to grounding and wiring problems.</i>	8
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	Math H. Bollen, " Understanding Power Quality Problems ", Wiley-IEEE Press.	1st	1999
2.	G. T. Heydt Stars " Electric Power Quality ", Circle Publishers.	2nd	1994
	Reference Books		
1.	J. Arrillaga, " Power System Quality Assessment ". John Wiley.	2nd	2000
2.	Surya Santoso, H. Wayne Beaty, Roger C. Dugan, Mark F. McGranaghan, " Electrical Power System Quality ", McGraw Hills.	2nd	2002

12.	Mode of Evaluation	<i>Test / Quiz / Assignment / Mid Term Exam / End Term Exam</i>
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GRAPHIC ERA (DEEMED TO BE UNIVERSITY), DEHRADUN

SEMESTER III

S. No.	Department of Electronics and Communication Engineering						
1.	Subject Code	VDM 396		Course Title		Optimal & Adaptive Control	
2.	Contact Hours	L	3	T	0	P	0
3.	Examination Duration	Theory		3		Practical	
4.	Relative Weight	CIE	25	MSE	25	SEE	50
6.	Credit	03					
6.	Semester	Third					
7.	Category of Course	PE					
8.	Pre-requisite	Basic Electrical Engineering					

9.	Course Outcomes	<p>After completion of the course the students will be able to:</p> <p>CO1: Describe performance index and to define various optimal control problems.</p> <p>CO2: Extend knowledge of discrete linear regulator problem using dynamic programming.</p> <p>CO3: Apply the conditions for optimality and to solve continuous time linear regulator problem.</p> <p>CO4: Examine minimum time and minimum control effort problems.</p> <p>CO5: Evaluate adaptive control problems and to learn the mathematical description of model reference adaptive systems.</p> <p>CO6: Design adaptive systems using various techniques.</p>
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10. Details of the Course

S. No.	Contents	Contact Hours
1.	<p>Unit 1: Problem Formulation: Mathematical model, Physical constraints, Characteristics of the plants, Performance Measure, optimal control problems, selection of performance measure, state regulator problem, output regulator problem.</p> <p>Calculus of Variations: Fundamental concepts, minimization of functions, minimization of Functionals, Lagrange multiplier approach, constrained extrema, Variational approach to optimal control problems, formulation of variational calculus using Hamiltonian Method.</p>	09
2.	<p>Unit 2: Dynamic Programming: Optimal control law, Principle of optimality, principle of causality, principle of invariant imbedding, a recurrence relation of dynamic programming – computational procedure, Hamilton-Jacobi equation, and its application, one dimensional regulator problem and its solution using dynamic programming computational procedure.</p>	08
3.	<p>Unit 3: Optimization Problems & Techniques: Pontryagin's minimum principle, control & state variable inequality constraints, A nonlinear Reactor model problem and its solution, Minimum time problems, Minimization of functions, minimization of Functionals, two point boundary value problems.</p>	08

4.	Unit 4: Adaptive Control (Identifier based & Non Identifier based): Applications, Linear feedback, effects of process disturbances, robustness, adaptive schemes and various adaptive control strategies, Parametric models, Parameter identification (One Parameter Case & two Parameter Case).	08
5.	Unit 5: Model – Reference Adaptive System (MRAS) & Gain Scheduling:- MRAS: MIT Rule, Lyapunov Theory, Design of MRAS using Lyapunov Theory, Relation between MRAS and STR, Non-Linear System: Feedback Linearization, Adaptive Feedback Linearization, Back-stepping, Adaptive Back-stepping with tuning functions, Design of Gain- Scheduling Controllers.	09
	Total	42

11. Suggested Books

S. No.	Name of Authors/Books/Publishers	Edition	Year of Publication / Reprint
	Textbooks		
1.	Donald E. Kirk, “ Optimal Control Theory: An Introduction ”, Prentice-Hall networks series, 10th Edition, 1970.	1 st	1970
2.	Anderson B. D. O, Moore J. B, “ Optimal control linear Quadratic methods ”, Prentice Hall of India,	1 st	1991
	Reference Books		
1.	Sage A. P, White C. C, “ Optimum Systems Control ” Prentice Hall.	2 nd	1977
2.	Athans M and P L Falb, “ Optimal Control-An Introduction to the Theory and its Applications ”, McGraw Hill Inc,	2 nd	1966

12.	Mode of Evaluation	Test / Quiz / Assignment / Mid Term Exam / End Term Exam
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